



集成电路原理与设计

MOS器件

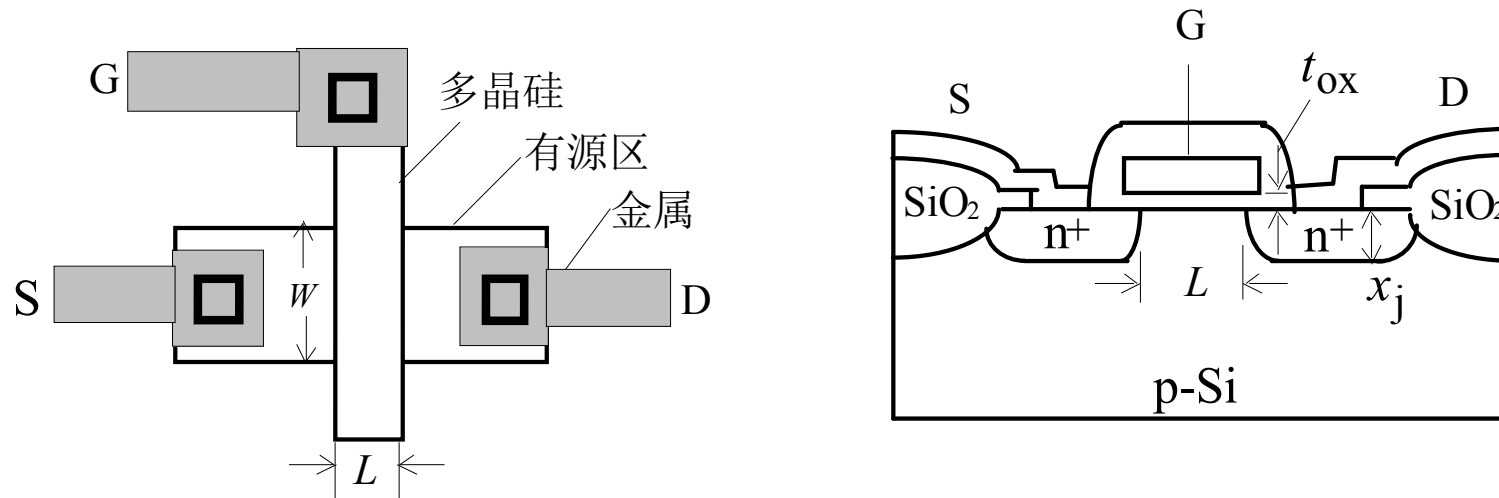


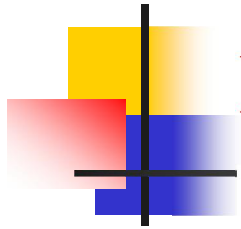
长沟道MOS器件模型

- **3.1.1 MOS**晶体管阈值电压分析
- **3.1.2 MOS**晶体管电流方程
- **3.2.1 MOS**晶体管的亚阈值电流
- **3.2.2 MOS**晶体管的瞬态特性
- **3.2.3 MOS**器件模型

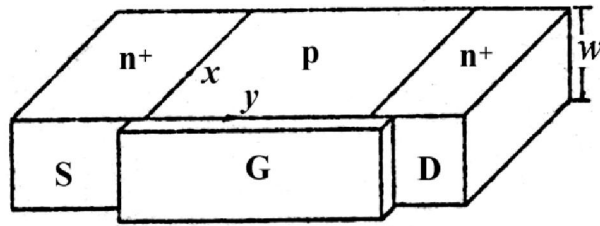
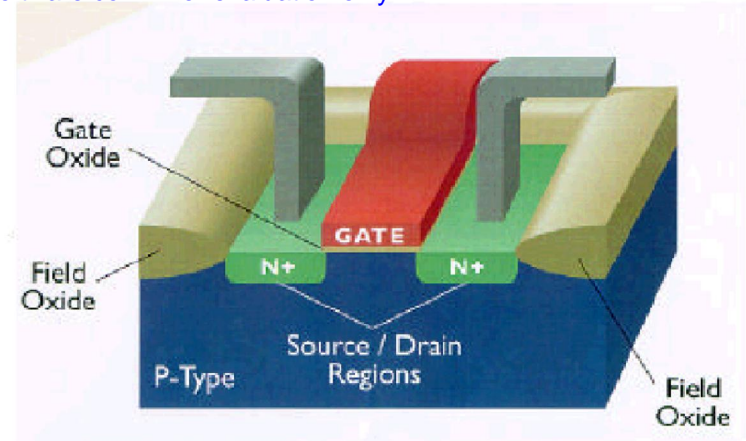
MOS晶体管的结构和原理

MOS晶体管的结构

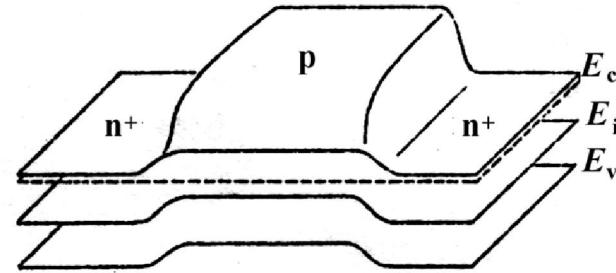




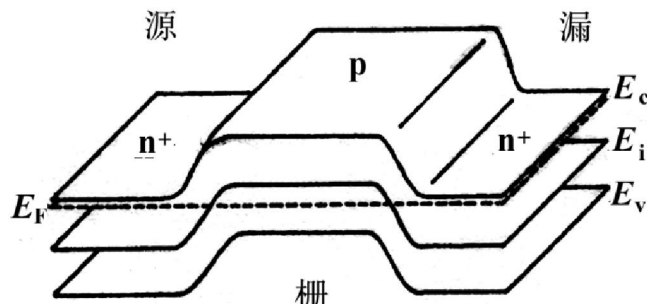
MOS晶体管工作原理



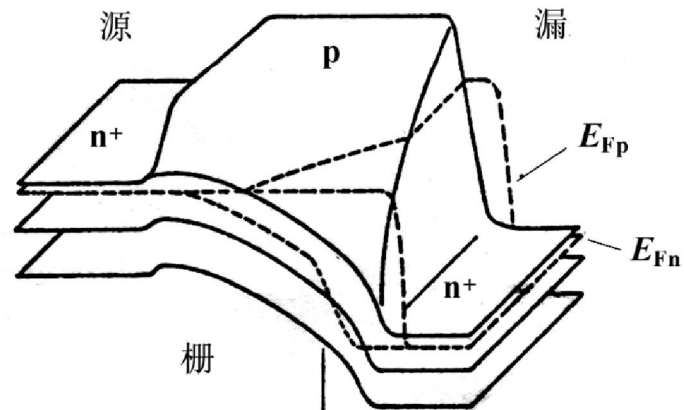
(a)



(c)



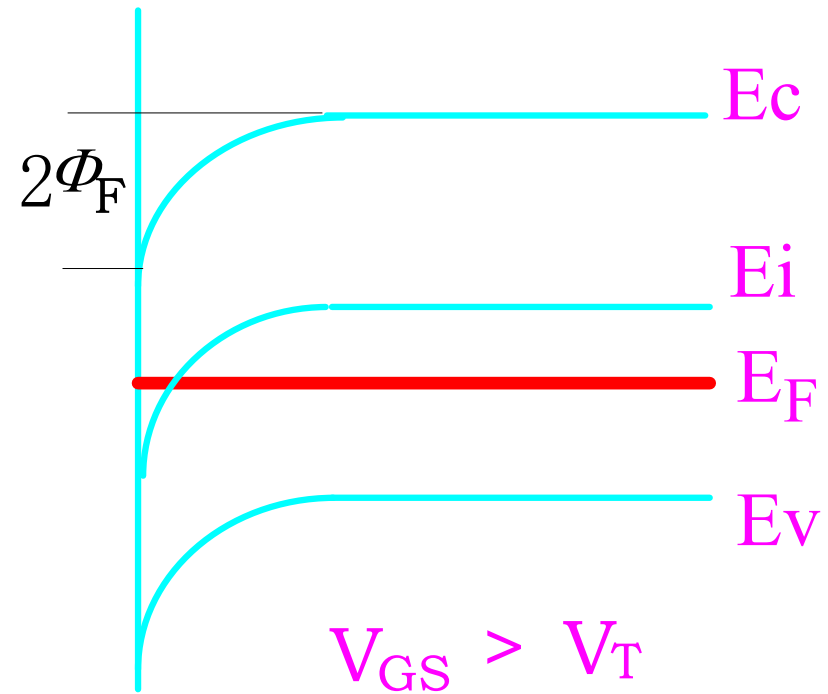
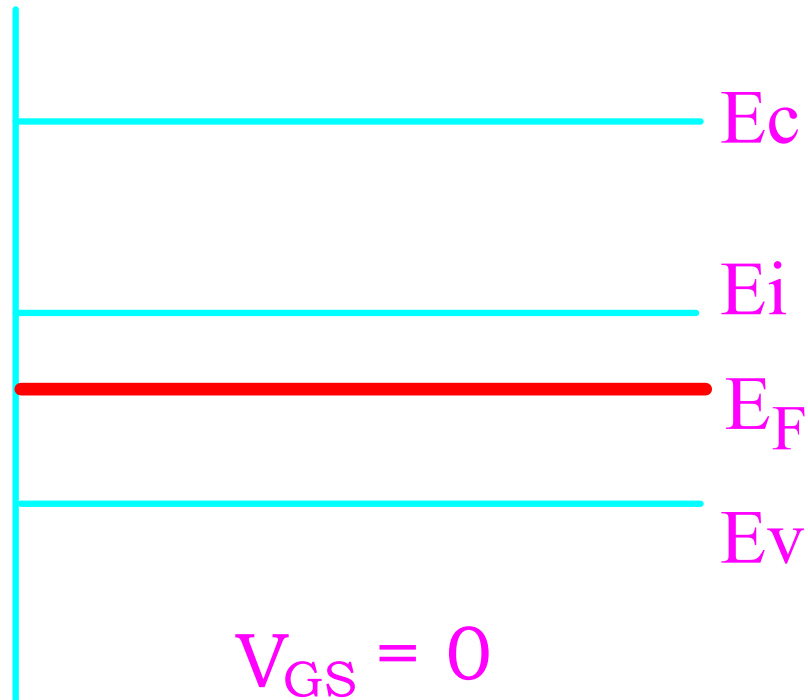
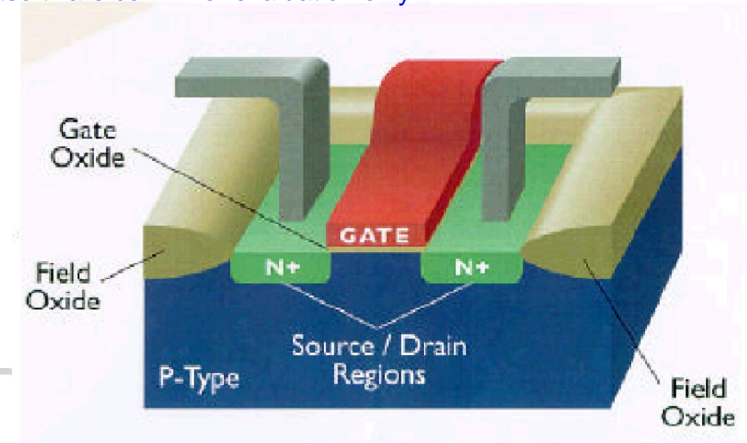
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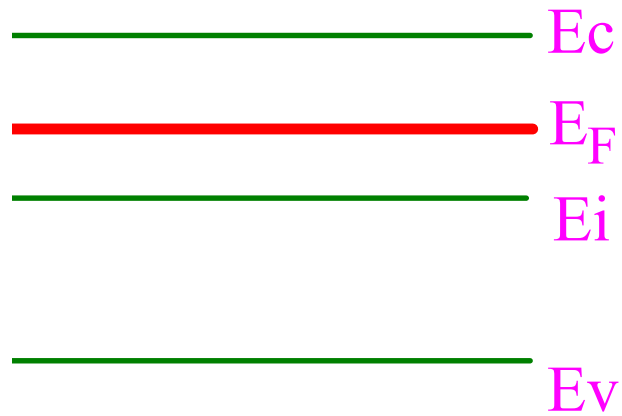
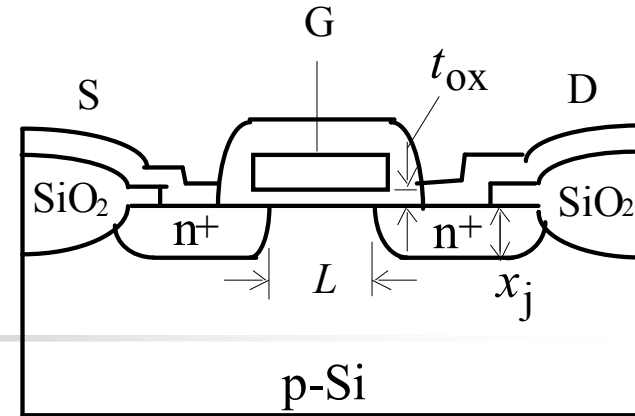
(d)

漏耗尽区

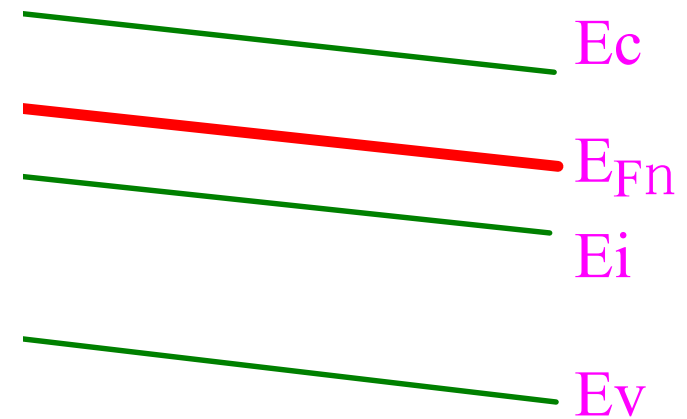
垂直方向能带图



沿沟道方向能带图

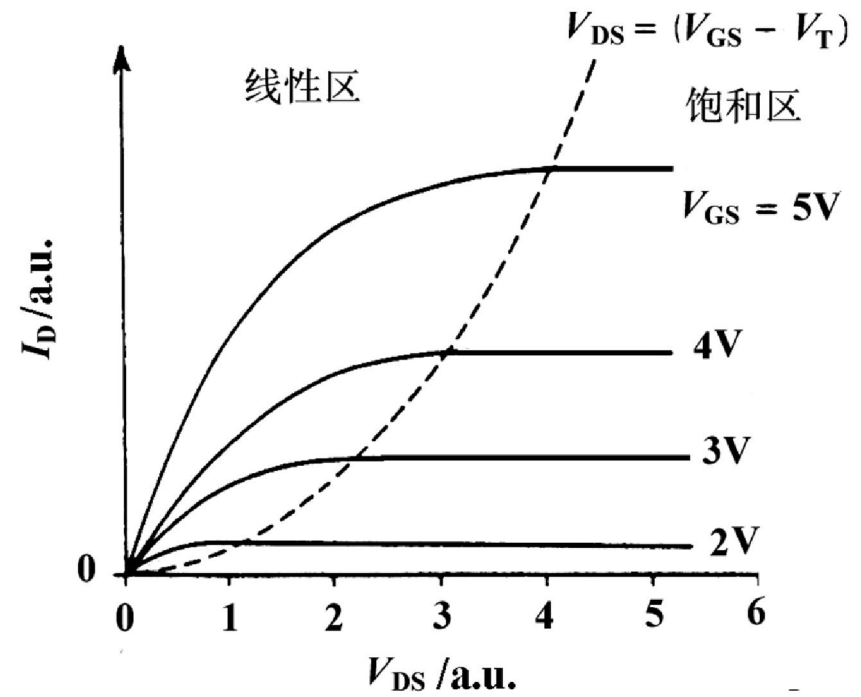
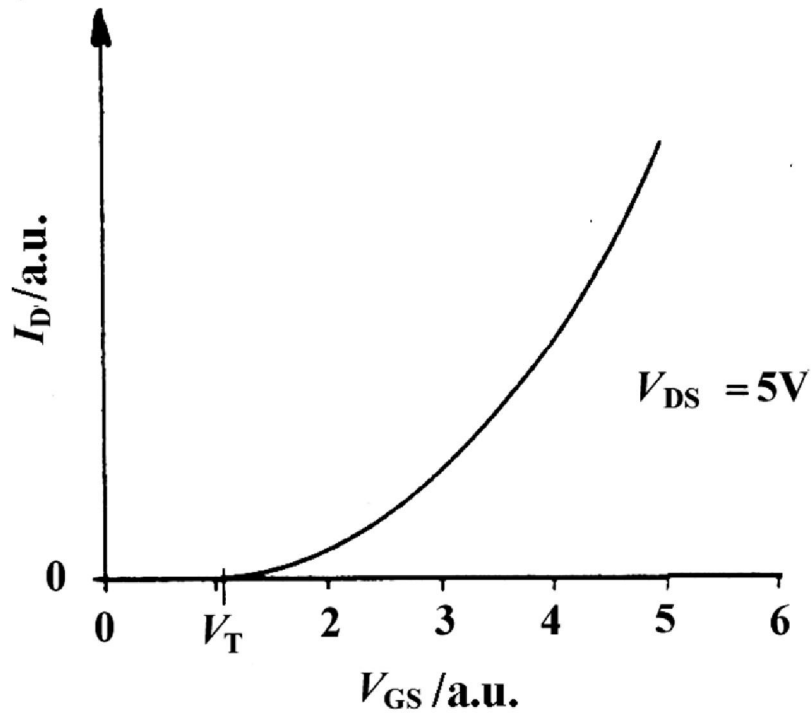


$$V_{DS} = 0$$



$$V_{DS} > 0$$

MOSFET的输入、输出特性曲线



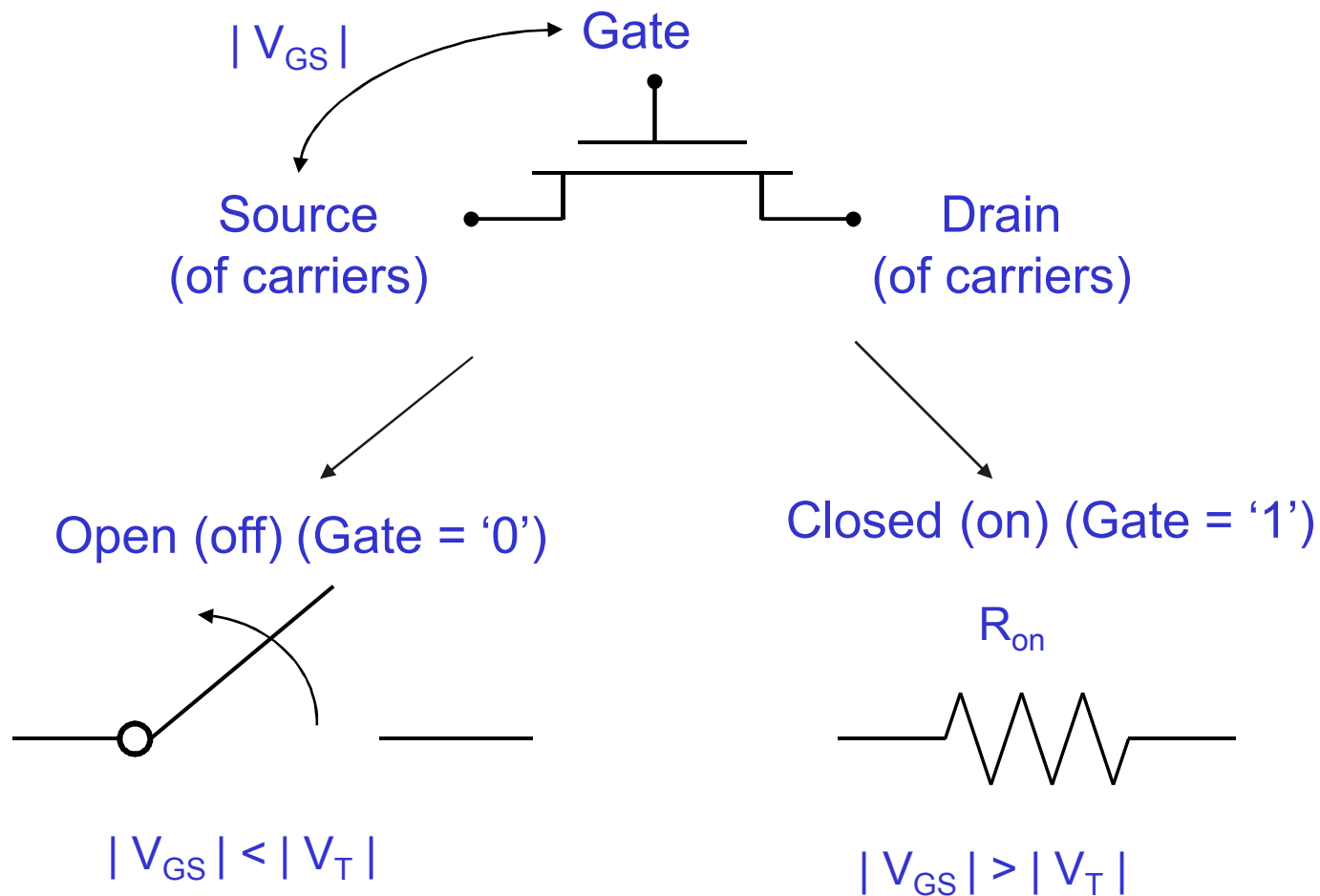
MOS晶体管阈值电压分析



阈值电压的定义:

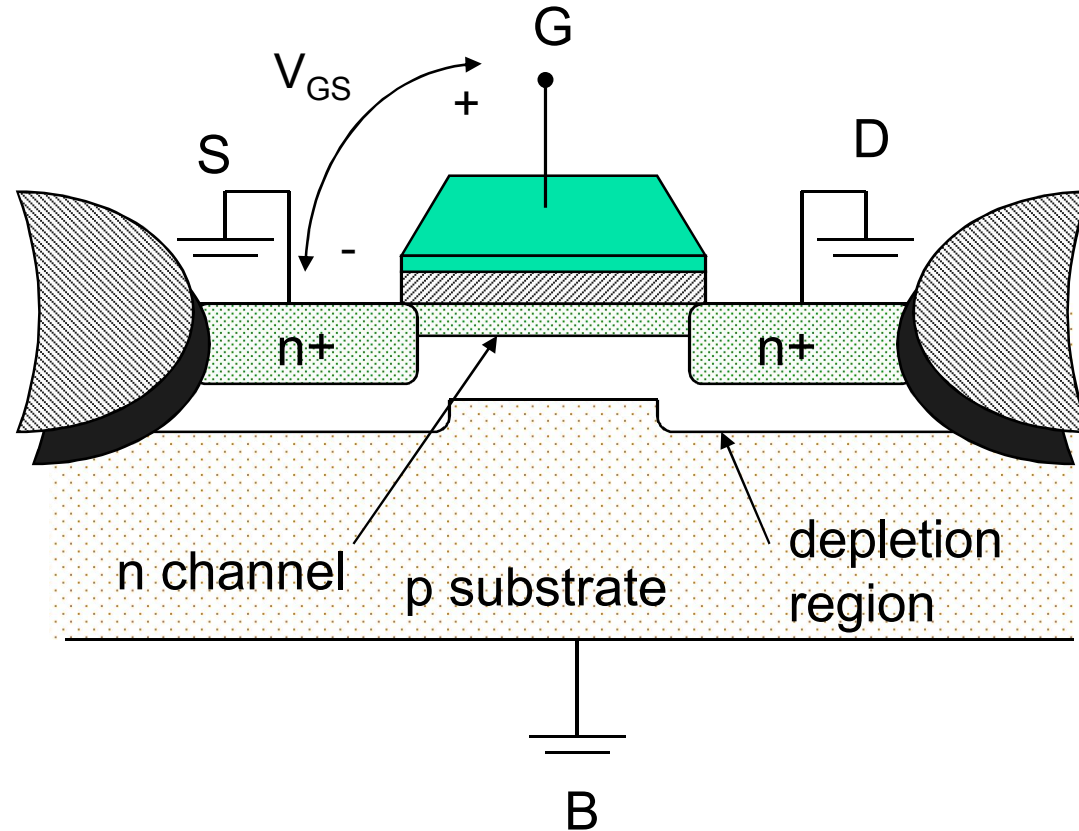
使源端半导体表面达到强反型的栅压，是区分MOS器件导通和截止的分界点。

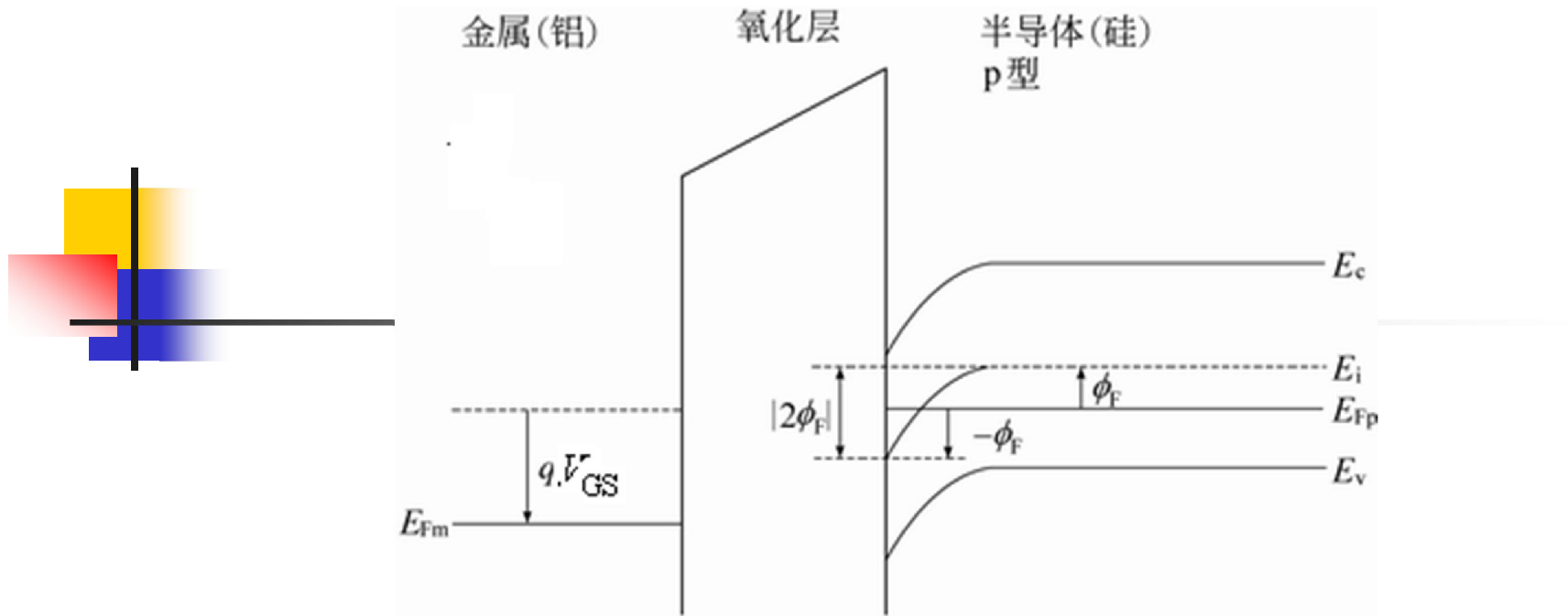
Switch Model of NMOS Transistor



半导体表面达到强反型的 栅压-- V_T

阈值电压





1、阈值电压公式(假设NMOS源端和衬底接地)

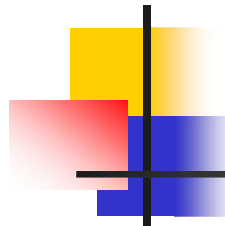
$$V_T = V_{FB} + V_{ox} + \phi_s$$

V_{FB} 对应半导体平带电压

V_{ox} 对应栅氧化层上的压降

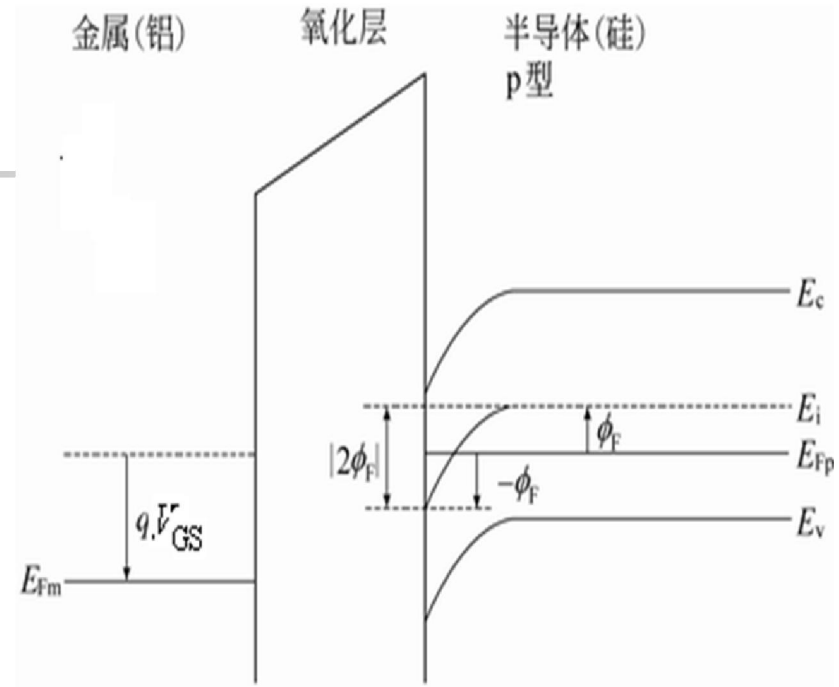
ϕ_s 对应半导体表面耗尽层上的压降

阈值电压：耗尽层压降—表面势


$$V_T = V_{FB} + V_{ox} + \varphi_s$$

$$V_T = V_{FB} + 2\varphi_F - \frac{Q_{Bm}}{C_{ox}}$$

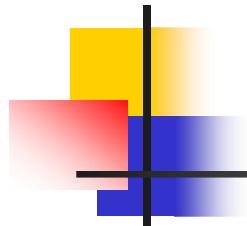
φ_F 是衬底费米势

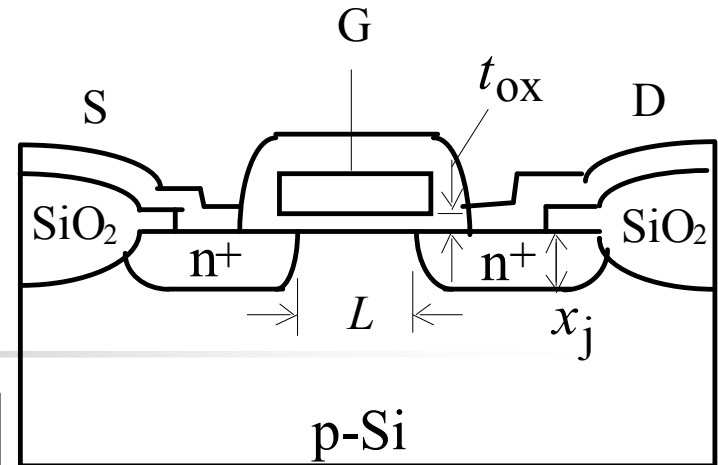


$$\varphi_F = (kT/q) \ln(N_A/n_i) \quad (\text{NMOS})$$

$$\varphi_F = -(kT/q) \ln(N_D/n_i) \quad (\text{PMOS})$$

阈值电压：氧化层压降


$$V_T = V_{FB} + V_{ox} + \phi_s$$



$$V_T = V_{FB} + 2\phi_F - \frac{Q_{Bm}}{C_{ox}}$$

Q_{BM}/C_{ox} 对应栅氧化层上的压降 (NMOS)

$$Q_{BM} = -[2\epsilon_0\epsilon_{Si}qN_A(2\phi_F)]^{1/2}$$

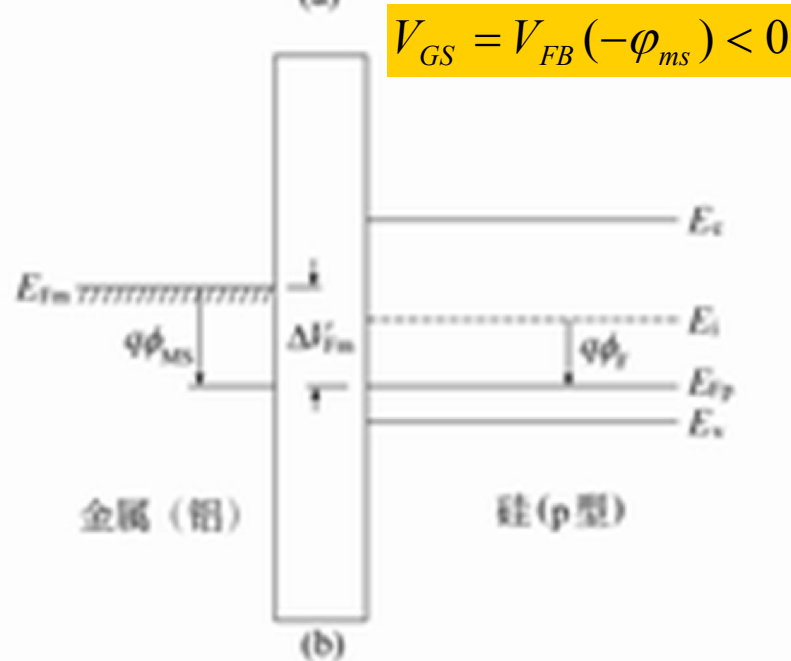
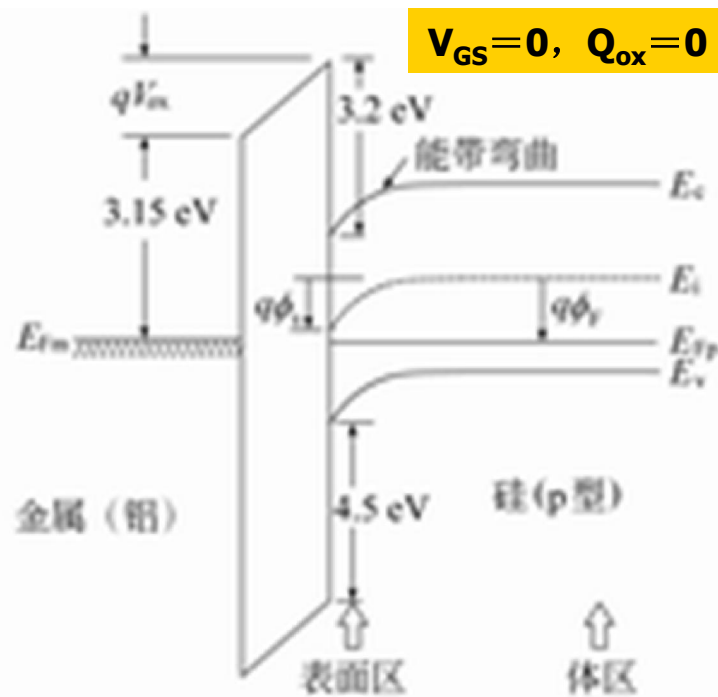
$$C_{ox} = \epsilon_0\epsilon_{ox}/t_{ox}$$

V_{FB} : 半导体平带电压

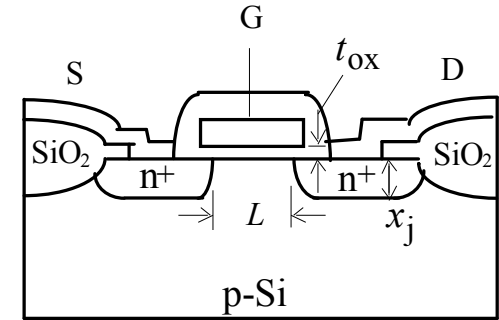
$$V_T = V_{FB} + 2\phi_F - \frac{Q_{Bm}}{C_{ox}}$$

$$V_{FB} = \phi_{MS} - \frac{Q_{ox}}{C_{ox}}$$

- 栅氧化层中的可动电荷和固定电荷以及界面态电荷
- 栅材料和硅衬底之间的功函数差
- 外加栅压抵消这部分能带弯曲，使得能带恢复平直，称为平带电压



体效应对阈值电压的影响



衬底偏压 V_{BS} 的影响

- 假设衬底和源端等电位
- 如果衬底和源端之间有电压，阈值电压会发生变化，也称为衬偏效应

$$V_T = V_{FB} + 2\phi_F + \gamma \sqrt{2\phi_F - V_{BS}}$$

$$\gamma = \frac{\sqrt{2\epsilon_0 \epsilon_{Si} q N_A}}{C_{ox}}$$

衬底偏压 V_{BS} 对阈值影响

- **NMOS**器件一般加负的衬底偏压，即 $V_{BS} < 0$ ，保证源和衬底之间pn结反偏隔离
- 这样耗尽层展宽，阈值电压公式中耗尽层电荷增加，阈值电压增加

$$Q'_{Bm} = -\sqrt{2\varepsilon_0\varepsilon_{si}qN_A(2\phi_F - V_{BS})}$$

$$V_T = V_{FB} + 2\phi_F - \frac{Q'_{Bm}}{C_{ox}}$$

体效应对阈值电压的影响

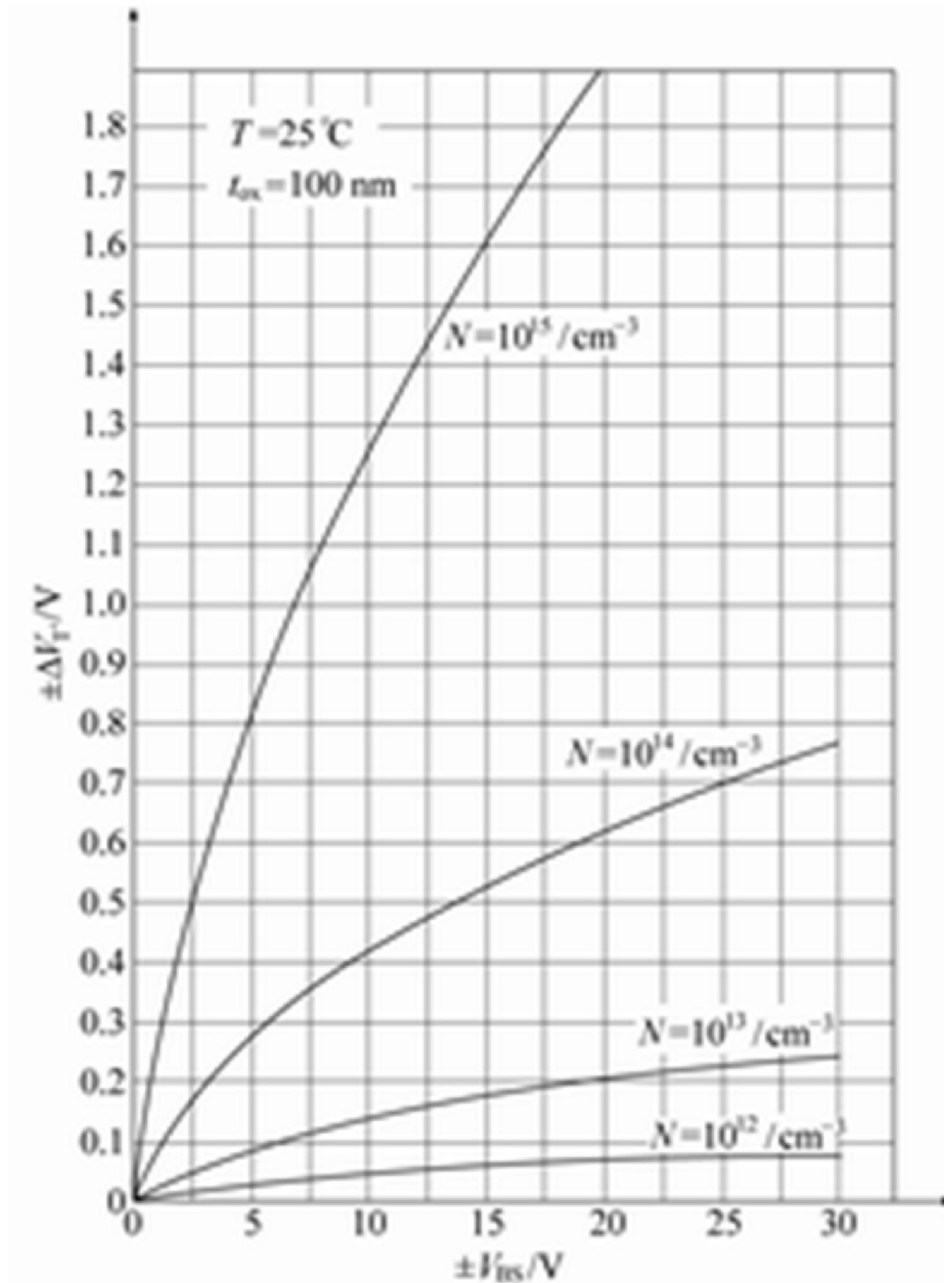
- 引入体效应因子 $V_T = V_{FB} + 2\phi_F + \gamma \sqrt{2\phi_F - V_{BS}}$
- 带衬偏电压的阈值电压公式
$$\gamma = \frac{\sqrt{2\varepsilon_0 \varepsilon_{Si} q N_A}}{C_{ox}}$$
- 体效应引起的阈值电压变化
$$\Delta V_T = V_T - V_{T0} = \gamma(\sqrt{2\phi_F - V_{BS}} - \sqrt{2\phi_F})$$
$$V_{T0} = V_{FB} + 2\phi_F + \gamma \sqrt{2\phi_F}$$

$$V_T = V_{FB} + 2\phi_F + \gamma\sqrt{2\phi_F - V_{BS}} - V_{BS}$$

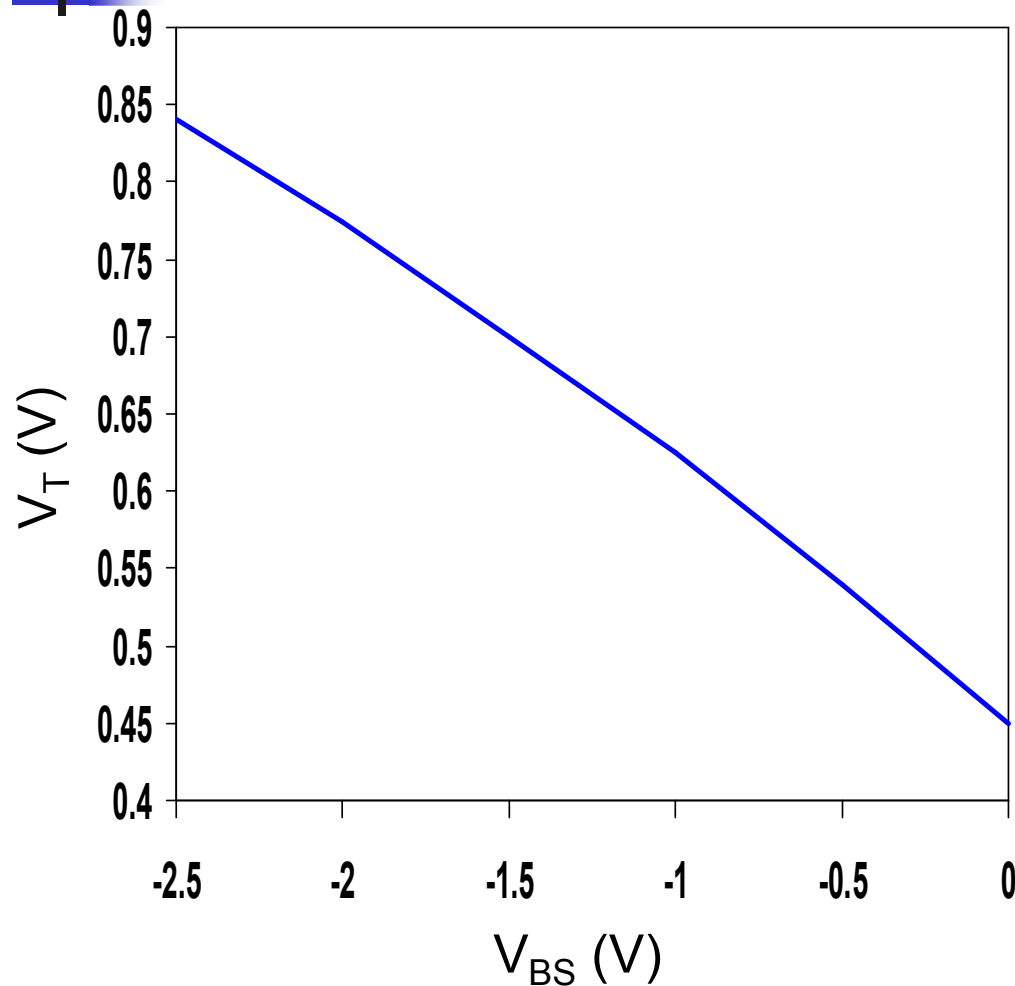
$$\Delta V_T = V_T - V_{T0} = \gamma(\sqrt{2\phi_F - V_{BS}} - \sqrt{2\phi_F})$$

$$\gamma = \frac{\sqrt{2\varepsilon_0\varepsilon_{Si}qN_A}}{C_{ox}}$$

- 不同衬底掺杂浓度下，衬底偏压引起阈值电压的变化



The Body Effect



- A negative bias $V_{bs} = 2.5V$, causes V_T to increase from 0.45V to 0.85V

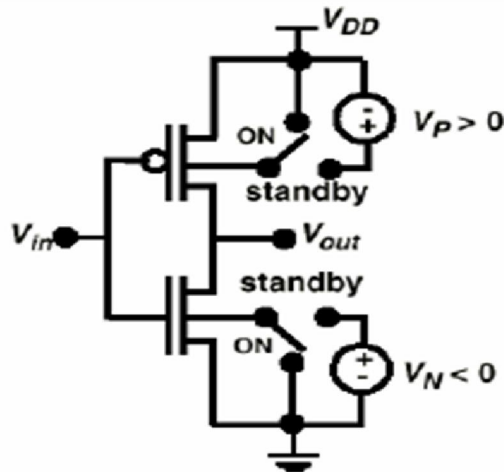


体效应的应用

- 电路中不是所有器件的源和衬底均能够短接，这个时候体效应引起阈值电压的变化，影响电路性能
- 动态阈值控制电路中，利用衬底偏压调节阈值，满足高速和低功耗不同应用的需要

VTCMOS: 可变阈值的方法

- 利用MOS器件的体效应，通过调整衬底偏压动态改变器件的阈值电压



Substrate Bias Controlled
Variable V_T Devices -
(Increase V_T during idle periods)

from [Seta95] (ISSCC 1995)

- 正向偏置FBB（Forward Body Bias），对NMOS器件来说，源端接地，则提高衬底电位，降低阈值
- 反向偏置RBB（Reverse Body Bias），提高阈值，降低静态泄漏
- 零偏置ZBB（Zero Body Bias），正常使用，不加衬底偏置



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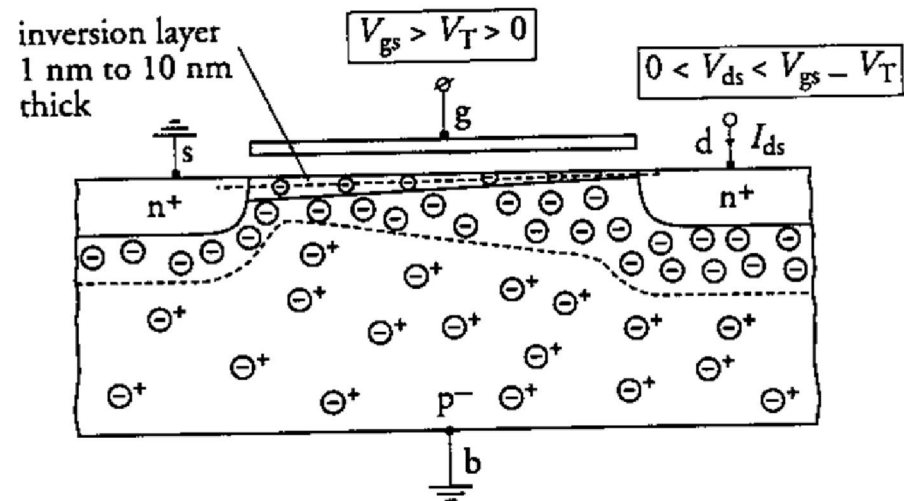
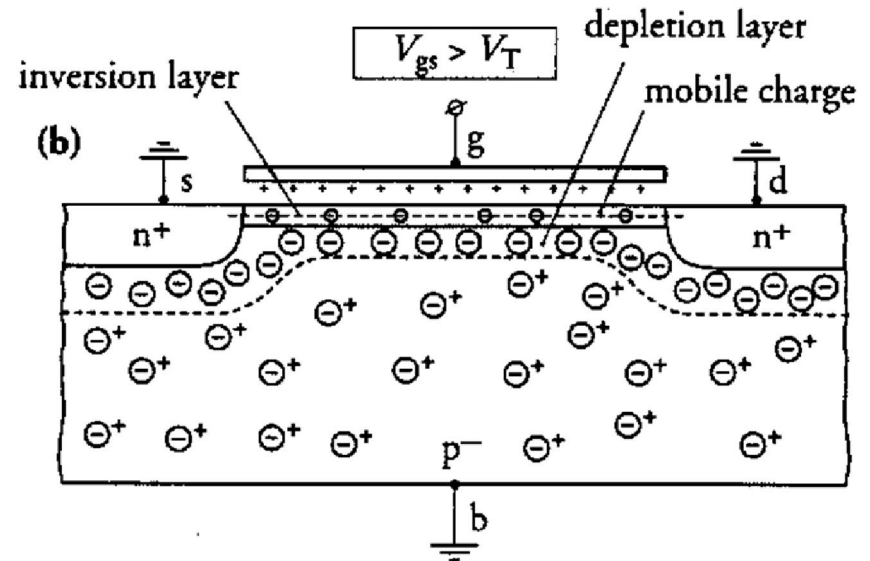


3.1.2 MOS晶体管的电流电压特性

- 漏电压对MOS特性的影响
- 简单电流方程
- 亚阈值区电流方程

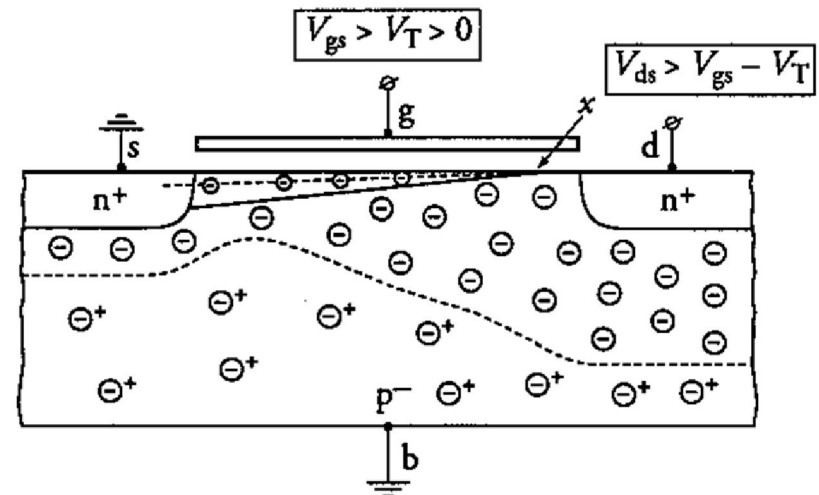
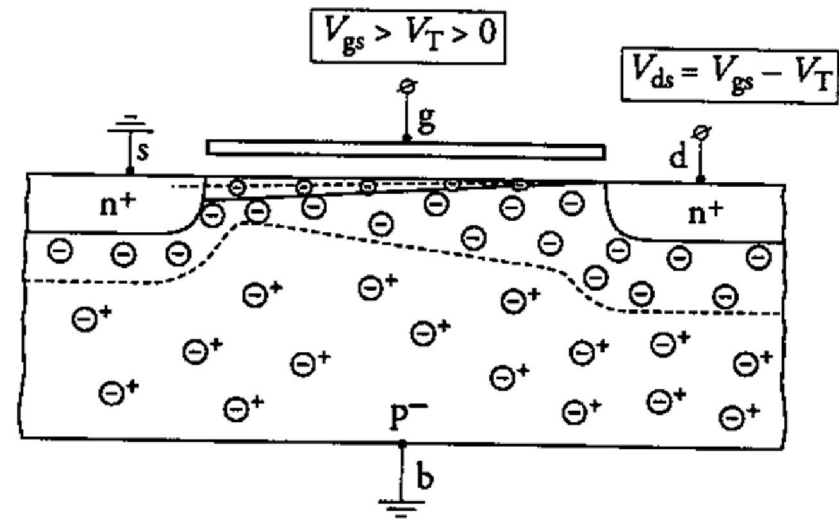
1、漏电压对MOS特性的影响

- 栅电压高于阈值电压，沟道区形成导电沟道
- 加上漏电压 V_{ds} ，形成横向电场，**NMOS**沟道电子定向运动
- 线性区

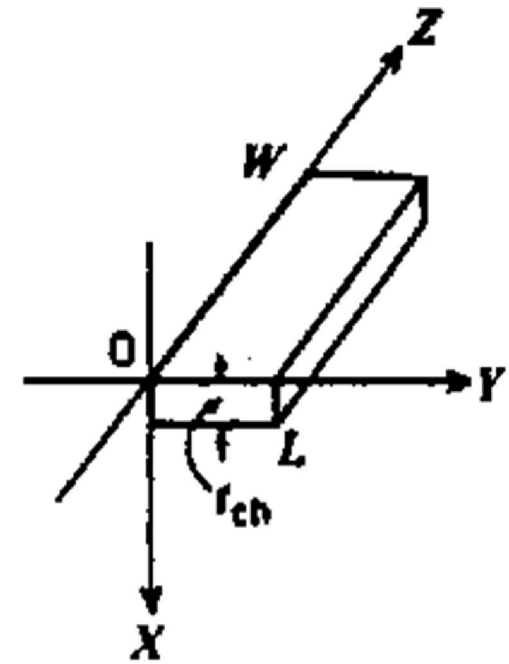
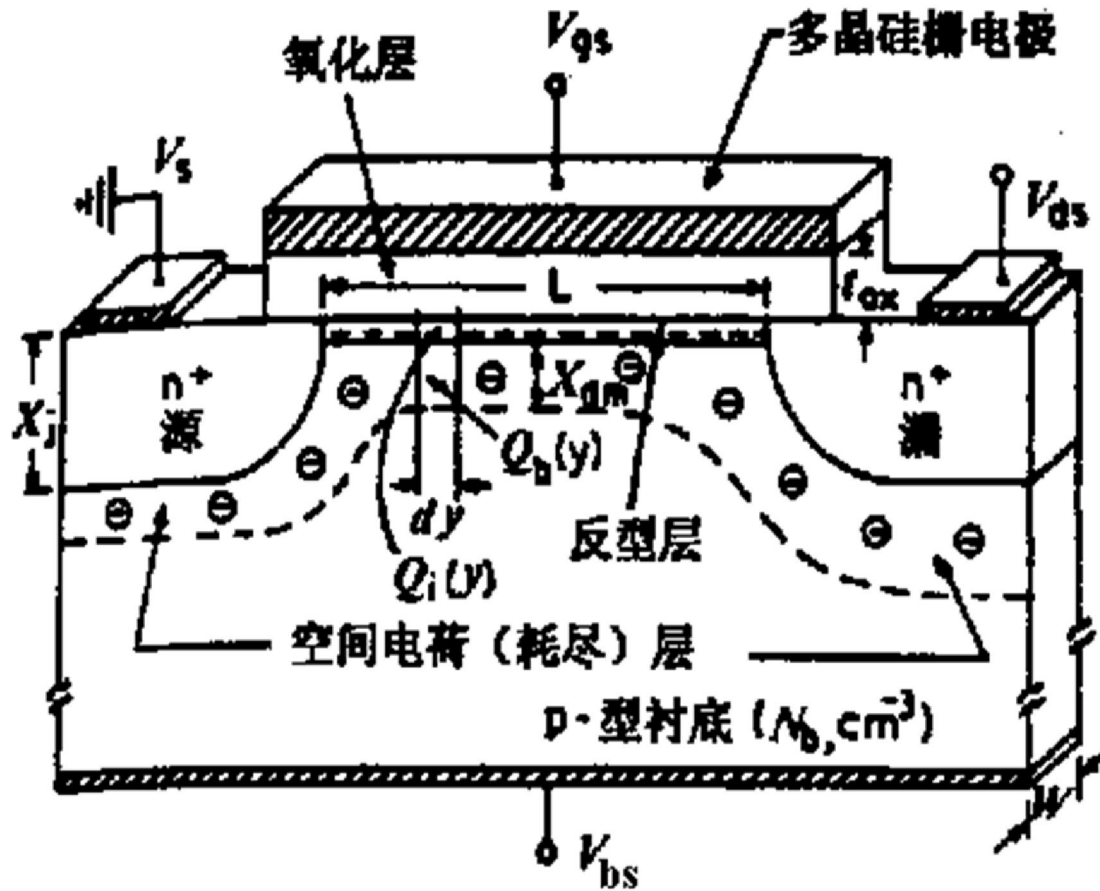


漏电压对MOS特性的影响

- 漏压不断增加，反偏pn结耗尽区不断扩展
- 漏压达到夹断电压，漏端沟道夹断
- 饱和区



2 简单电流方程

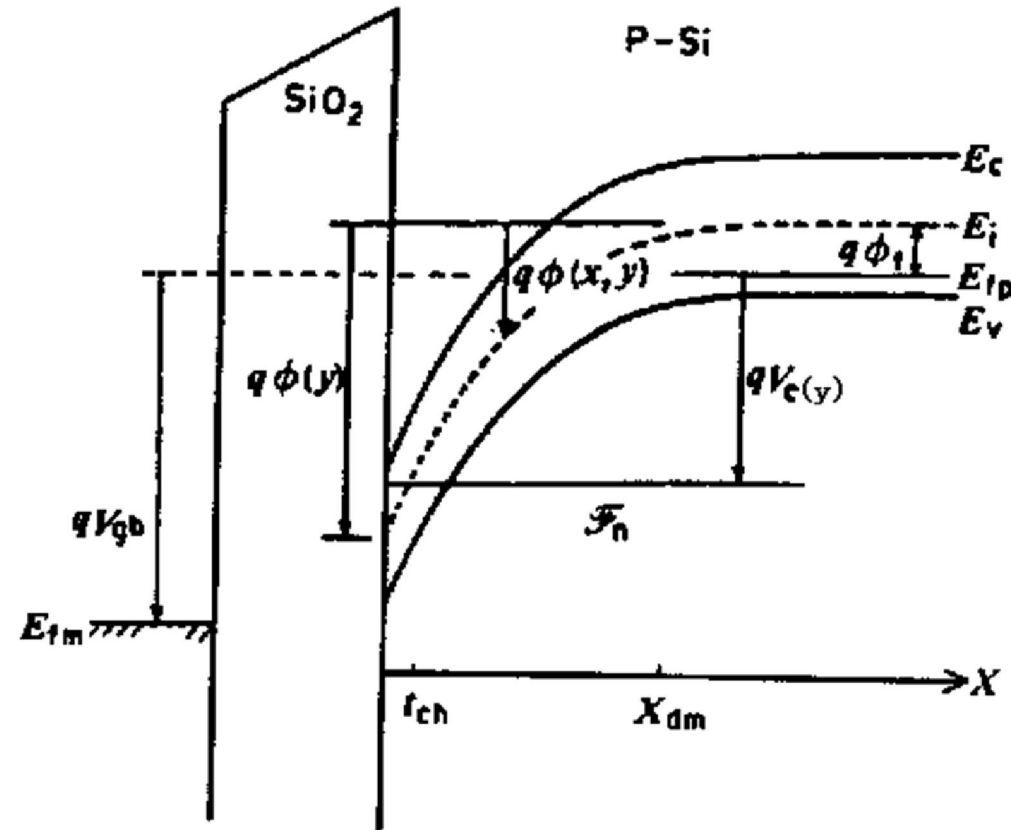




推导电流方程的一些近似处理

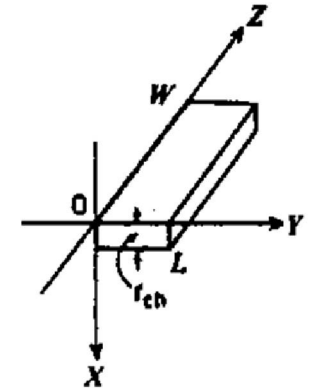
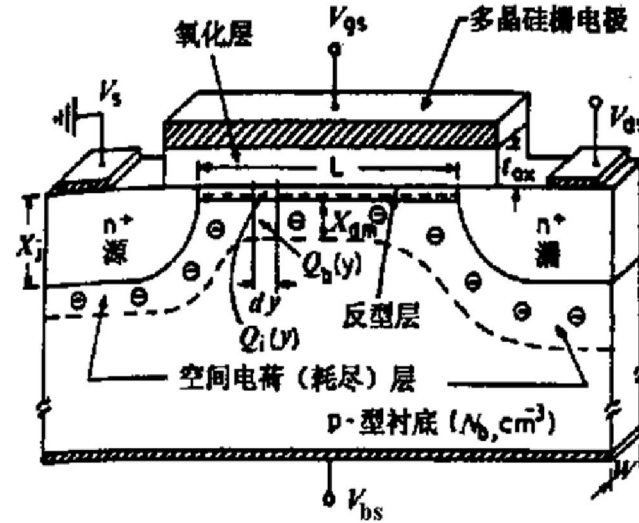
- 缓变沟道近似
- 强反型近似
- 只考虑漂移运动，忽略扩散电流
- 假定载流子的表面迁移率是常数
- 利用薄层电荷近似

MOS晶体管沟道中y点的能带图



根据高斯定理:

源端和衬底接地



$$Q_s(y) = -\epsilon_0 \epsilon_{si} E_x = -C_{ox} V_{ox}(y)$$

$$V_{ox}(y) = V_{GS} - V_{FB} - 2\phi_F - V(y)$$

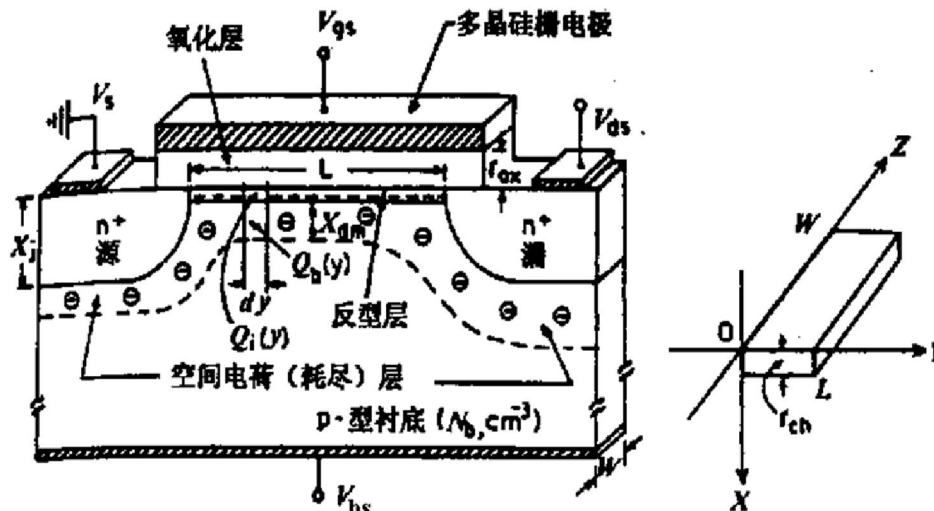
$$Q_c(y) = Q_s(y) - Q_B(y) \approx Q_s(y) - Q_{Bm}$$

$$= -C_{ox} \left[V_{GS} - V_{FB} - 2\phi_F - V(y) + \frac{Q_{Bm}}{C_{ox}} \right]$$

$$= -C_{ox} [V_{GS} - V_T - V(y)]$$

根据欧姆定律:

- 对电流公式进行积分，其中 $V_c(y)$ 是漏电压沿沟道方向的电压降
- 漏压较小的时候，沟道连续 ($0-L$)， $V_c(y)$ 为 ($0-V_{ds}$)
- 得到线性区电流方程



$$I_D = W \mu_{eff} |Q_c(y)| \frac{dV(y)}{dy},$$

$$Q_c(y) = -C_{ox} (V_{GS} - V_T - V_c(y))$$

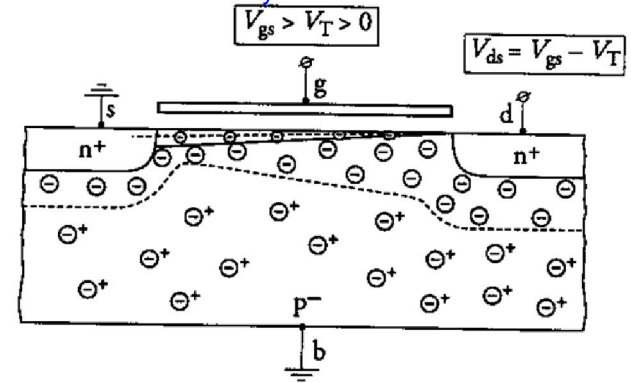
在 V_{DS} 较小时，从源到漏都存在导电沟道，
根据电流连续，两边积分得到线性区电流：

$$\text{线性区电流: } I_D = \beta \left[(V_{GS} - V_T) V_{DS} - \frac{1}{2} V_{DS}^2 \right]$$
$$\approx \beta (V_{GS} - V_T) V_{DS}, \quad V_{DS} \text{ 很小时。}$$

导电因子 β

$$\beta = \frac{W}{L} \mu_{eff} C_{ox}$$

饱和区电流



- 当漏压增大到一定程度，漏端沟道夹断，器件进入饱和区
- 夹断点处的电压称为漏饱和电压 $V_{Dsat} = V_{GS} - V_T$ ，代入线性区电流公式，得到饱和区电流

$$I_D = \beta \left[(V_{GS} - V_T) V_{DS} - \frac{1}{2} V_{DS}^2 \right]$$
$$\approx \beta (V_{GS} - V_T) V_{DS}, \quad V_{DS} \text{ 很小时。}$$

$$\beta = \frac{W}{L} \mu_{eff} C_{ox}$$

$$I_D = \frac{\beta}{2} (V_{GS} - V_T)^2$$

$$V_{Dsat} = V_{GS} - V_T$$

电流方程：端电压形式

$$I_D = K \left[(V_G - V_T - V_S)^2 - (V_G - V_T - V_D)^2 \right]$$

$$K = \frac{1}{2} \mu_{eff} C_{ox} \frac{W}{L} = \frac{1}{2} K' \frac{W}{L}, \quad K' = \mu_{eff} C_{ox}$$

- 导电因子：**K**因子
- 本征导电因子：**K'**
- 端电压形式的电流方程体现了**MOS**器件的源漏对称的特点

$$I_D = K \left[(V_G - V_T - V_S)^2 - (V_G - V_T - V_D)^2 \right]$$

$$K = \frac{1}{2} \mu_{eff} C_{ox} \frac{W}{L} = \frac{1}{2} K' \frac{W}{L}, \quad K' = \mu_{eff} C_{ox}$$

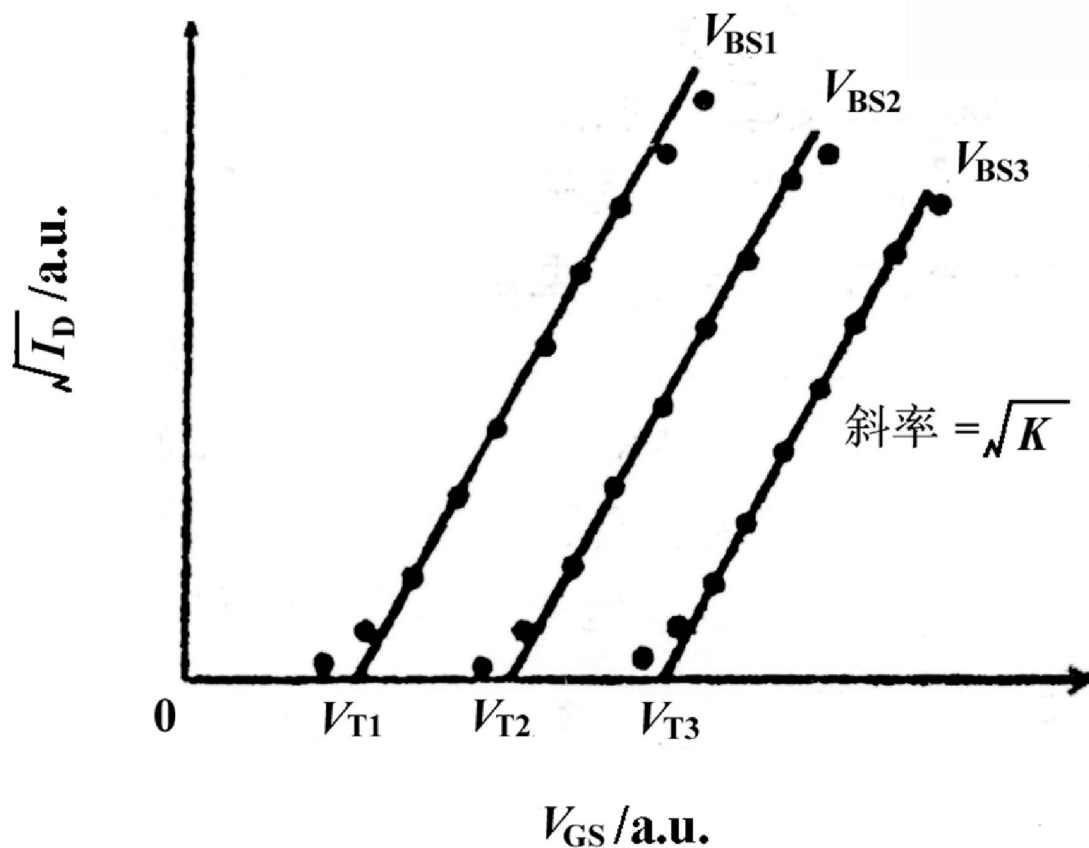
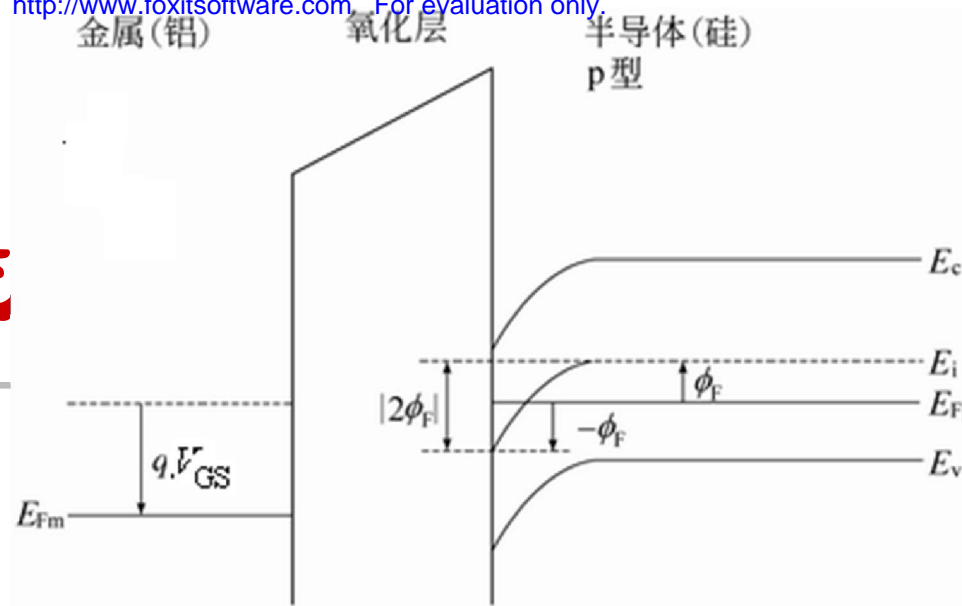
工作区	NMOS	PMOS
截止区	$(V_G - V_T - V_S) \leq 0$	$(V_G - V_T - V_S) \geq 0$
线性区	$(V_G - V_T - V_S) > 0$ $(V_G - V_T - V_D) > 0$	$(V_G - V_T - V_S) < 0$ $(V_G - V_T - V_D) < 0$
饱和区	$(V_G - V_T - V_S) > 0$ $(V_G - V_T - V_D) \leq 0$	$(V_G - V_T - V_S) < 0$ $(V_G - V_T - V_D) \geq 0$



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亚阈值区电流

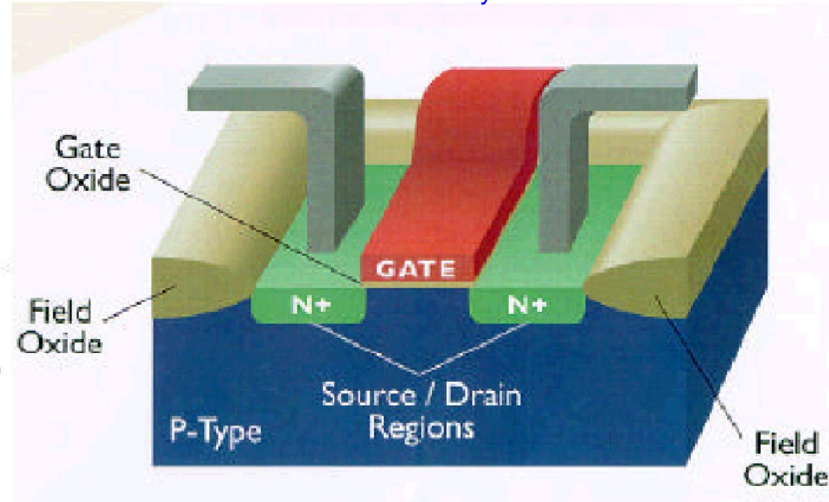


亚阈值区

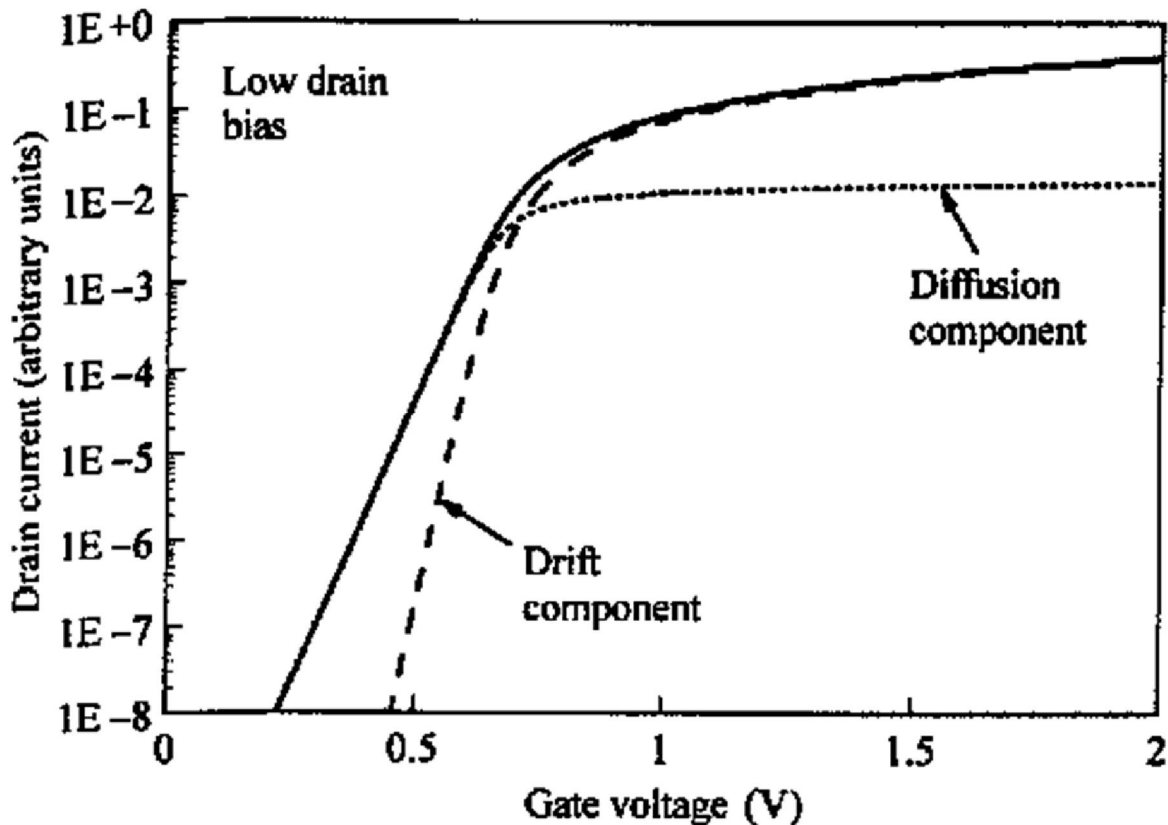
$$\phi_F < \phi_s \leq 2\phi_F$$

MOS表面弱反型

亚阈值电流特性



- 亚阈值区电流以载流子的扩散运动为主
- 弱反型的 **MOS** 表面相当于一个双极晶体管



亚阈电流

$$I_D = -qAD_n \frac{dn}{dy} = qAD_n \left[\frac{n(0) - n(L)}{L} \right]$$

其中 $D_n = \frac{kT}{q} \mu_n = V_t \mu_n$

反型层厚度：
表面势减小
一个 V_t 距离

$$A = W \cdot x_i, \quad x_i = \frac{V_t}{E_s}, \quad E_s = \sqrt{\frac{2qN_A \phi_s}{\epsilon_0 \epsilon_{si}}}$$

$$n(0) = n_{p0} \exp\left(\frac{q\phi_s}{kT}\right)$$

$$n(L) = n_{p0} \exp\left[\frac{q(\phi_s - V_{DS})}{kT}\right]$$

亚阈电流

$$E_s = \sqrt{\frac{2qN_A\phi_s}{\epsilon_0\epsilon_{si}}}$$

$$I_D = \frac{W}{L} \mu_n \left(\frac{kT}{q}\right)^2 \frac{q}{E_s} n_{p0} \exp\left(\frac{\phi_s}{V_t}\right) \left[1 - \exp\left(-\frac{V_{DS}}{V_t}\right)\right]$$

$$n_{p0} = \frac{n_i^2}{N_A}, \quad C_D = \sqrt{\frac{\epsilon_0\epsilon_{si}qN_A}{2\phi_s}}$$

$$I_D = \frac{W}{L} \mu_n V_t^2 C_D \left(\frac{n_i}{N_A}\right)^2 \exp\left(\frac{\phi_s}{V_t}\right) \left[1 - \exp\left(-\frac{V_{DS}}{V_t}\right)\right]$$

找出表面势与栅压的关系

$$V_{GS} = V_{FB} + \phi_s - \frac{Q_B}{C_{ox}}$$

$$Q_B = -[2\epsilon_0\epsilon_{Si}qN_A(\phi_s)]^{1/2}$$

$$\phi_s = V_{GS} - V_{FB} + \frac{\gamma^2}{2} \left[1 - \sqrt{1 + \frac{4}{\gamma^2} (V_{GS} - V_{FB})} \right]$$

$$I_D = \frac{W}{L} \mu_n V_t^2 C_D \left(\frac{n_i}{N_A} \right)^2 \exp\left(\frac{\phi_s}{V_t}\right) \left[1 - \exp\left(-\frac{V_{DS}}{V_t}\right) \right]$$

表面势和栅压的线性关系

$$V_{GS} = V_{FB} + \phi_s - \frac{Q_B}{C_{ox}}$$

- 对 $Q_B(\phi_s)$ 做泰勒展开：
$$Q_B(\phi_s) = Q_B(\phi_{s0}) + (\phi_s - \phi_{s0}) \frac{\partial Q_B}{\partial \phi_s}$$
$$= Q_B(\phi_{s0}) + (\phi_s - \phi_{s0}) C_D$$

$$V_{GS} = V_{FB} + \phi_{s0} + \frac{Q_B(\phi_{s0})}{C_{ox}} + (\phi_s - \phi_{s0}) \left(1 + \frac{C_D}{C_{ox}} \right)$$

$$V_{GS} = V_T + (\phi_s - 2\phi_F) \left(1 + \frac{C_D}{C_{ox}} \right),$$

$$\phi_s = 2\phi_F + \frac{V_{GS} - V_T}{n}, \quad n = 1 + \frac{C_D}{C_{ox}}$$

亚阈值电流

$$V_{GS} = V_T + (\phi_s - 2\phi_F) \left(1 + \frac{C_D}{C_{ox}} \right),$$

$$\phi_s = 2\phi_F + \frac{V_{GS} - V_T}{n}, \quad n = 1 + \frac{C_D}{C_{ox}}$$

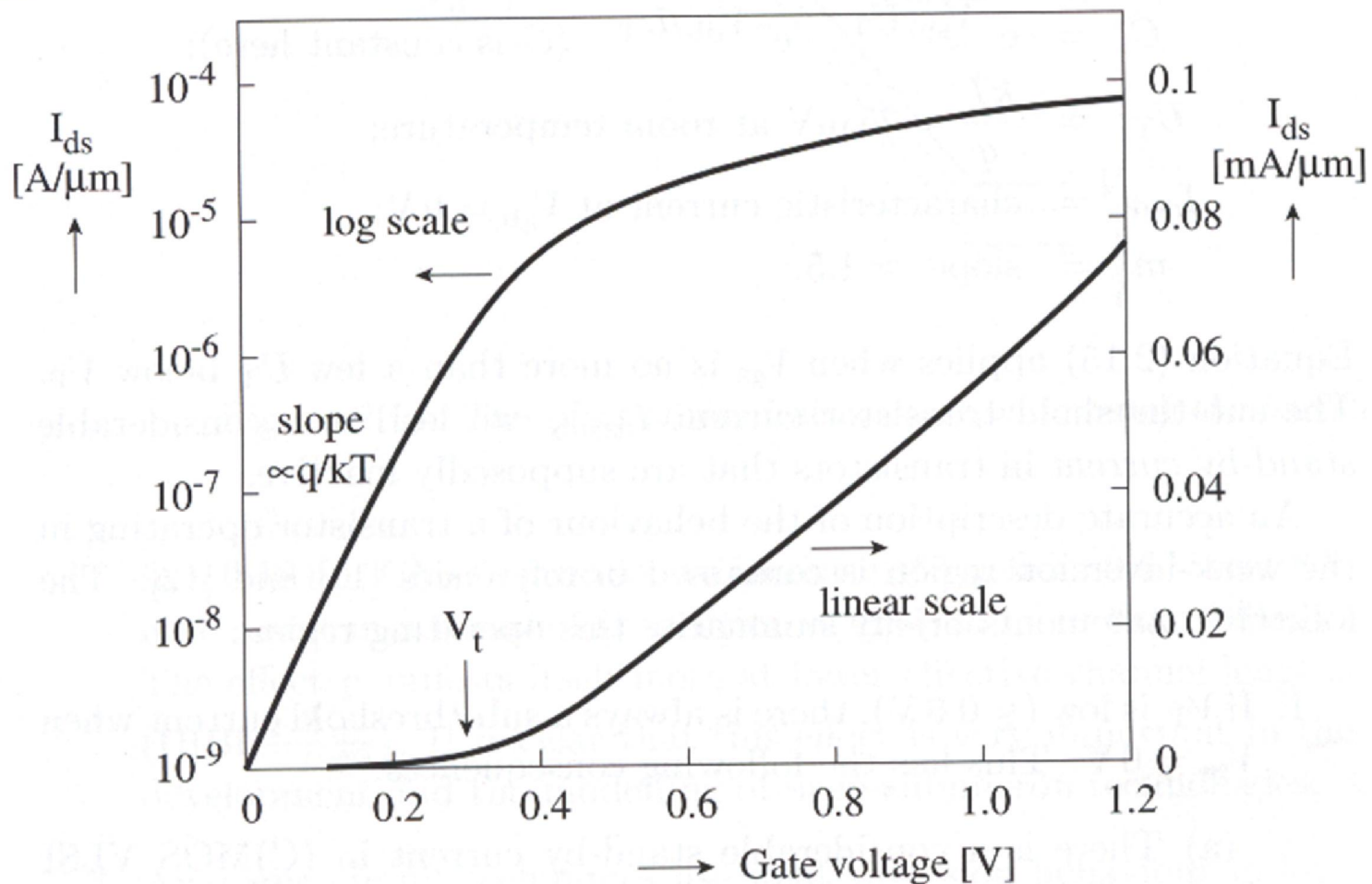
$$I_D = \frac{W}{L} \mu_n V_t^2 C_D \left(\frac{n_i}{N_A} \right)^2 \exp\left(\frac{\phi_s}{V_t}\right) \left[1 - \exp\left(-\frac{V_{DS}}{V_t}\right) \right]$$

$$I_D = I_0 \exp\left(\frac{V_{GS} - V_T}{nV_t}\right) \left[1 - \exp\left(-\frac{V_{DS}}{V_t}\right) \right] \approx I_0 \exp\left(\frac{V_{GS} - V_T}{nV_t}\right)$$

- 亚阈电流随着栅压指数变化
- 当漏压大于**3V_t**的时候，亚阈电流基本与漏压无关
- 亚阈电流同温度强烈相关

$$I_D = I_0 \exp\left(\frac{V_{GS} - V_T}{nV_t}\right) \left[1 - \exp\left(-\frac{V_{DS}}{V_t}\right)\right] \approx I_0 \exp\left(\frac{V_{GS} - V_T}{nV_t}\right)$$

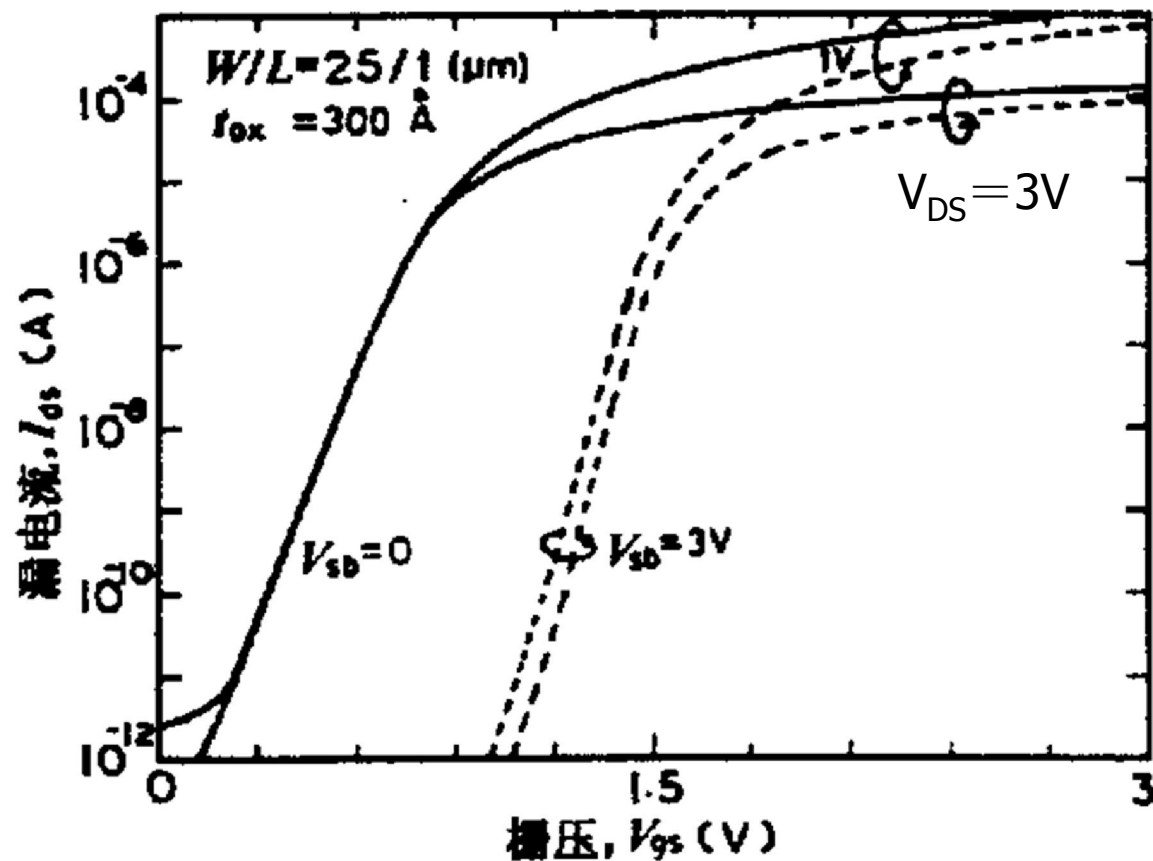
亚阈值电流



$$I_D = I_0 \exp\left(\frac{V_{GS} - V_T}{nV_t}\right) \left[1 - \exp\left(-\frac{V_{DS}}{V_t}\right)\right] \approx I_0 \exp\left(\frac{V_{GS} - V_T}{nV_t}\right)$$

亚阈值区电流特性

- 长沟器件，不同漏压的亚阈电流近似相等
- 衬底偏压对亚阈电流有影响



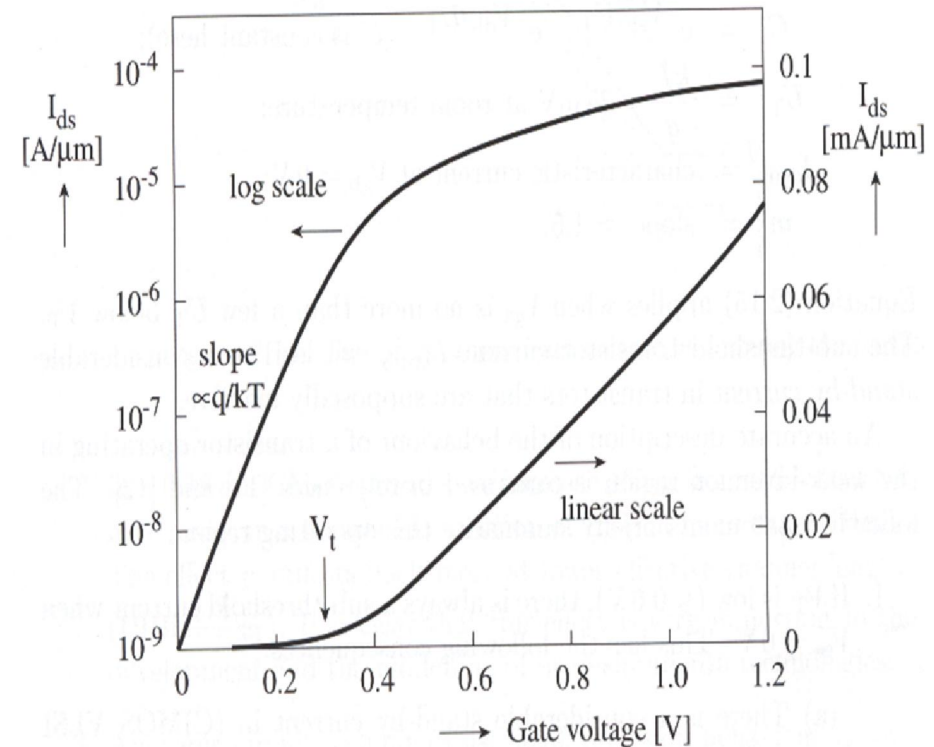
亚阈值斜率

$$I_D = I_0 \exp\left(\frac{V_{GS} - V_T}{nV_t}\right)$$

$$S = \frac{dV_{GS}}{d(\lg I_D)} = (\ln 10) \frac{dV_{GS}}{d(\ln I_D)} = (\ln 10)nV_t$$

$$n = 1 + \frac{C_D}{C_{ox}}$$

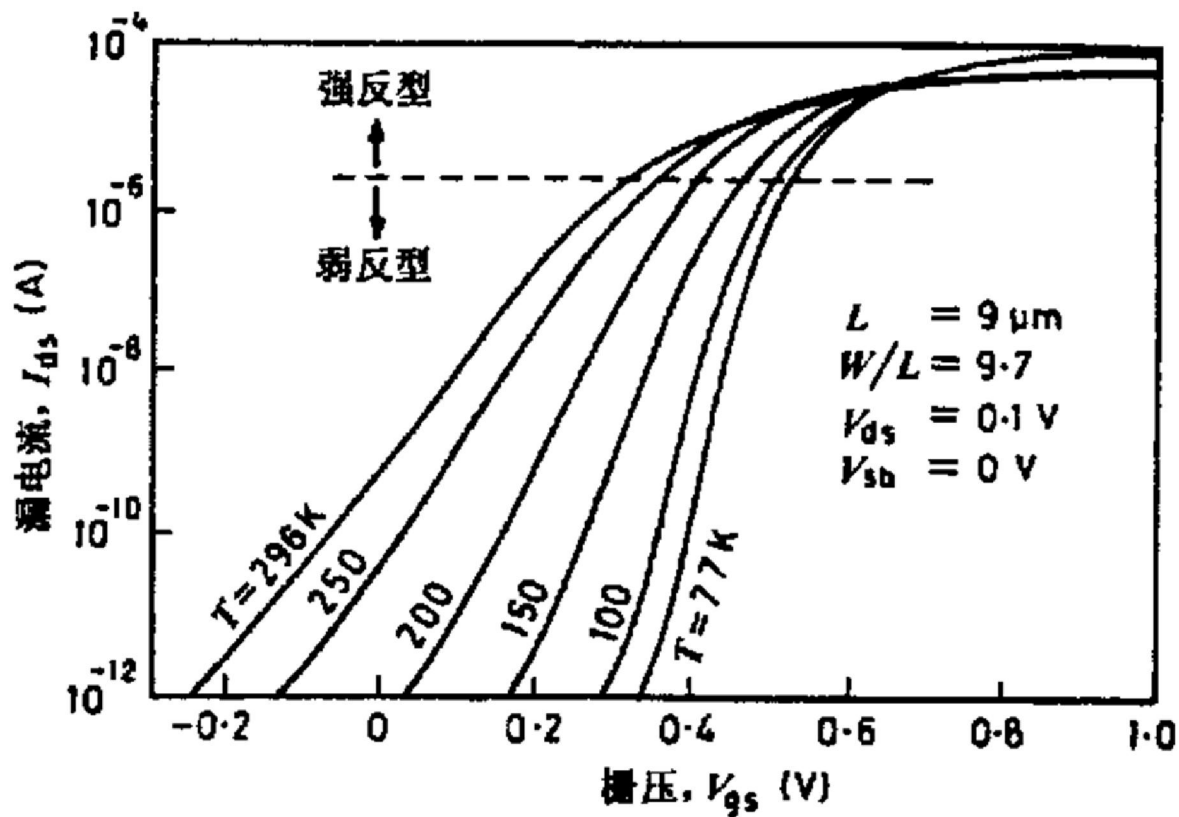
$$\therefore S = V_t (\ln 10) \left(1 + \frac{C_D}{C_{ox}}\right)$$



温度对亚阈值斜率的影响

$$n = 1 + \frac{C_D}{C_{ox}}$$

$$\therefore S = V_t (\ln 10) \left(1 + \frac{C_D}{C_{ox}} \right)$$

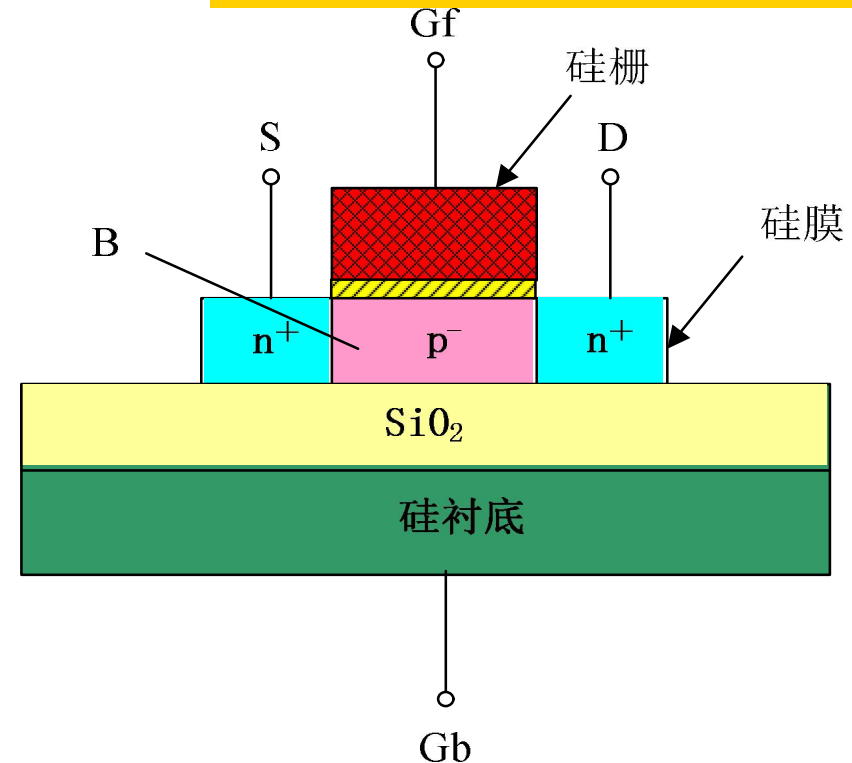


温度对亚阈值斜率的影响

$$n = 1 + \frac{C_D}{C_{ox}}$$

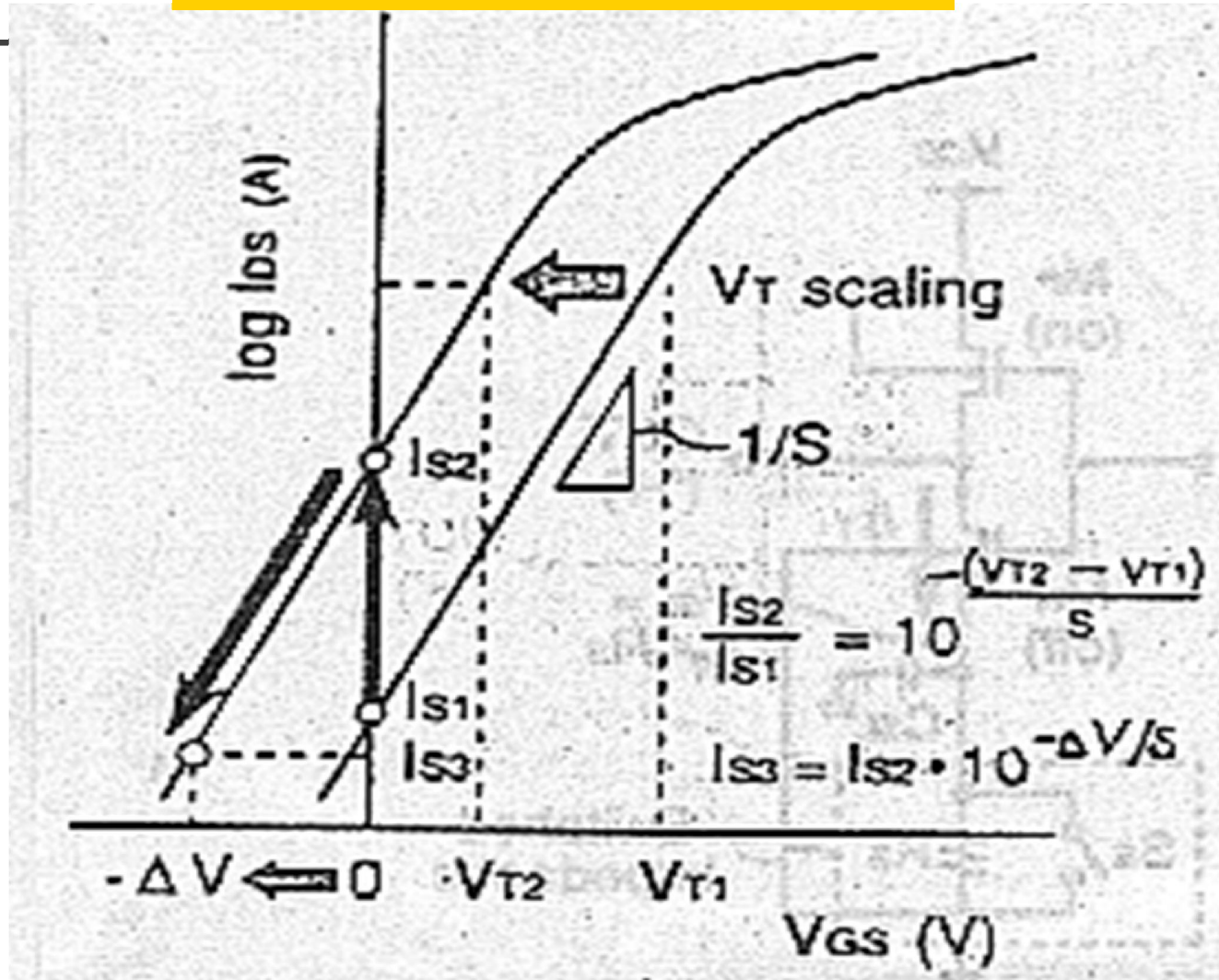
$$\therefore S = V_t (\ln 10) \left(1 + \frac{C_D}{C_{ox}} \right)$$

- 体硅的亚阈值斜率一般不小于**90mv/dec**
- 全耗尽SOI器件的亚阈值斜率可以接近理论极限值**60mv/dec**
- SOI器件基于更好的亚阈值特性



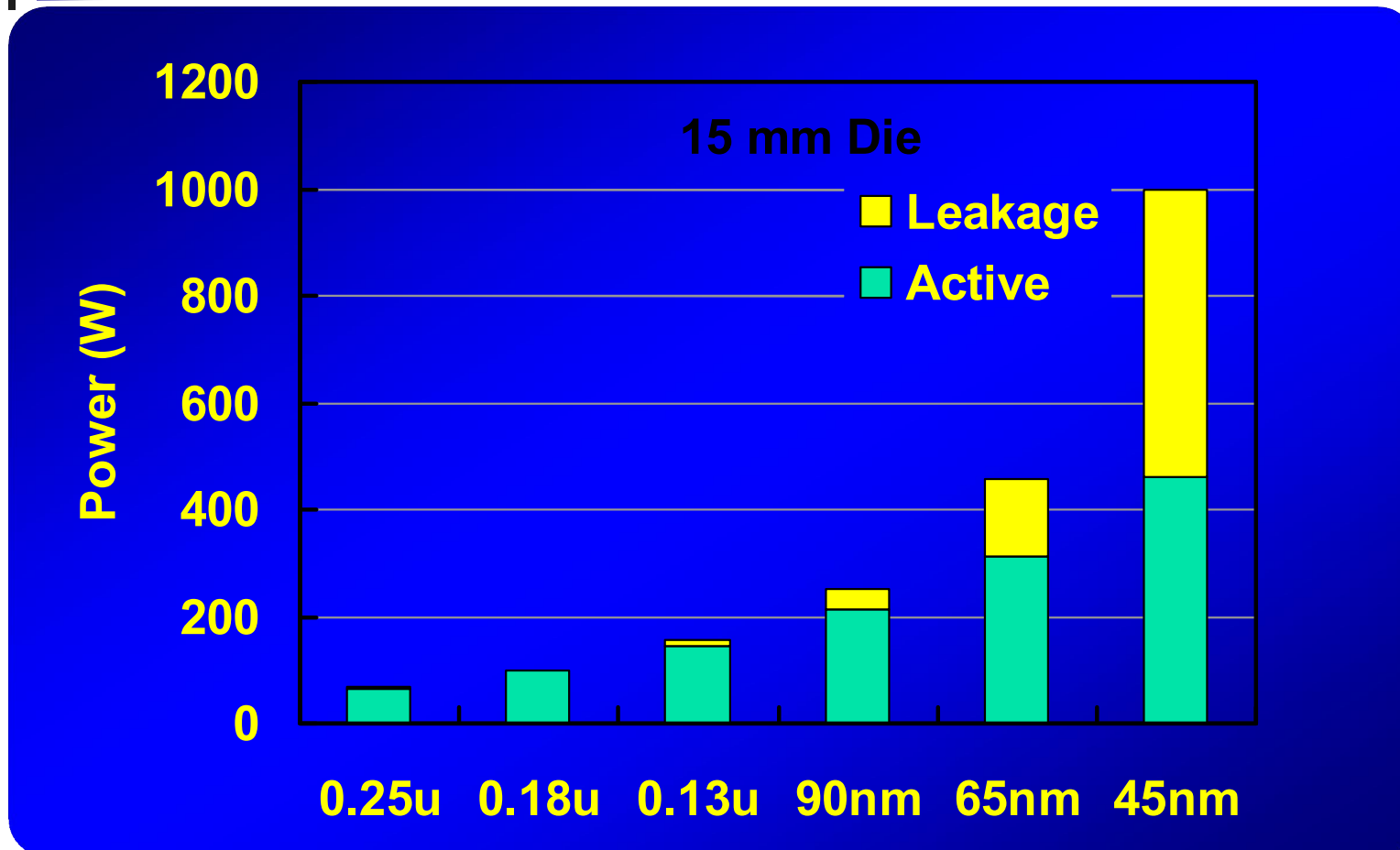
阈值电压对截止态电流的影响

$$I_D = I_0 \exp \left(\frac{V_{GS} - V_T}{nV_t} \right)$$



The Power Crisis

$$I_D = I_0 \exp\left(\frac{V_{GS} - V_T}{nV_t}\right)$$



低功耗工艺

	CL018 G	CL018 LP	CL018 ULP	CL018 HS	CL015 HS	CL013 HS
V_{dd}	1.8 V	1.8 V	1.8 V	2 V	1.5 V	1.2 V
T_{ox} (effective)	42 Å	42 Å	42 Å	42 Å	29 Å	24 Å
L_{gate}	0.16 μm	0.16 μm	0.18 μm	0.13 μm	0.11 μm	0.08 μm
I_{DSat} (n/p) (μA/μm)	600/260	500/180	320/130	780/360	860/370	920/400
I_{off} (leakage) (pA/μm)	20	1.60	0.15	300	1,800	13,000
V_{Tn}	0.42 V	0.63 V	0.73 V	0.40 V	0.29 V	0.25 V
FET Perf. (GHz)	30	22	14	43	52	80

From MPR, 2000



长沟道MOS器件模型

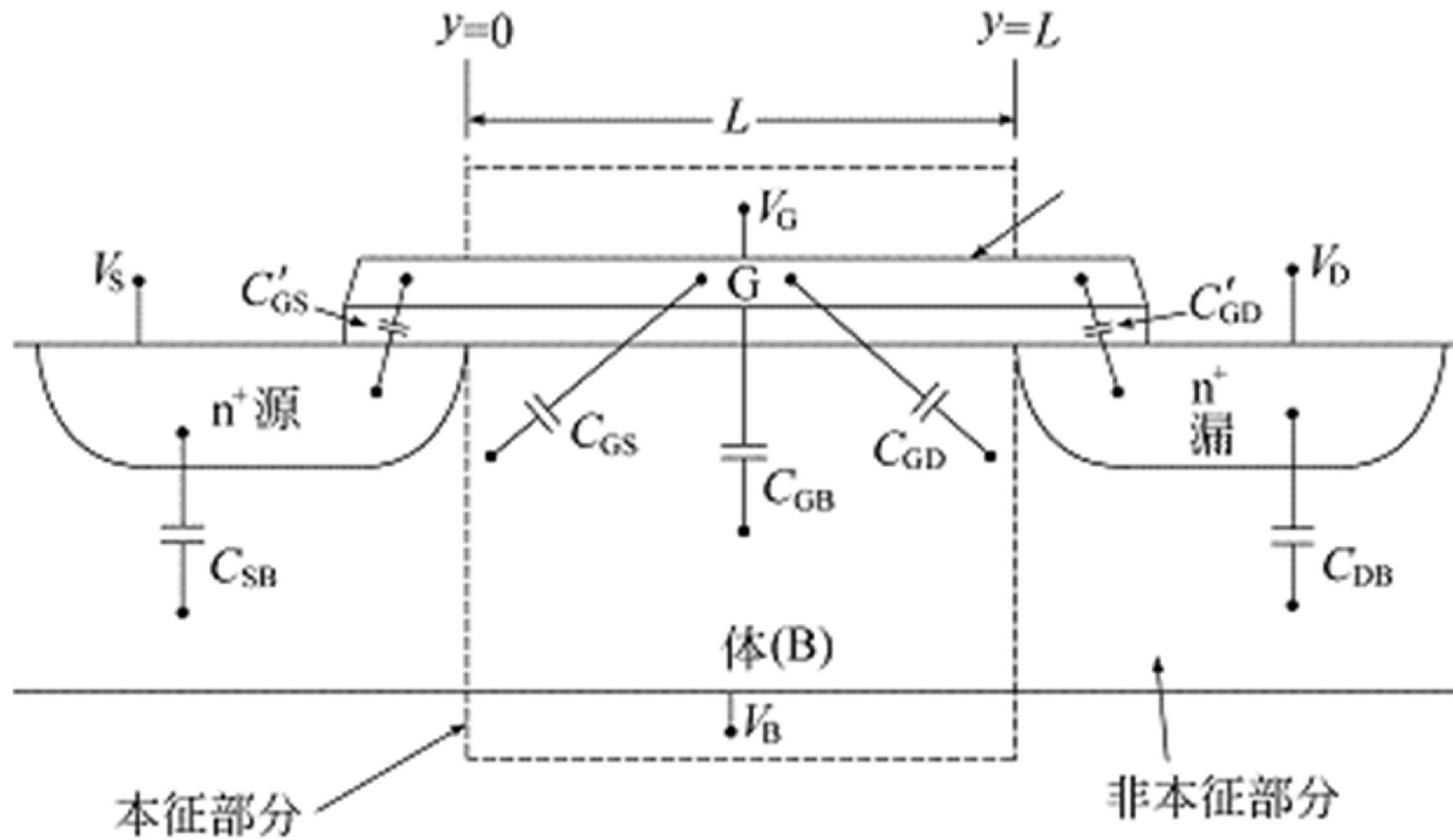
- **3.1.1 MOS**晶体管阈值电压分析
- **3.1.2 MOS**晶体管电流方程
- **3.2.1 MOS**晶体管的亚阈值电流
- **3.2.2 MOS**晶体管的瞬态特性
- **3.2.3 MOS**器件模型



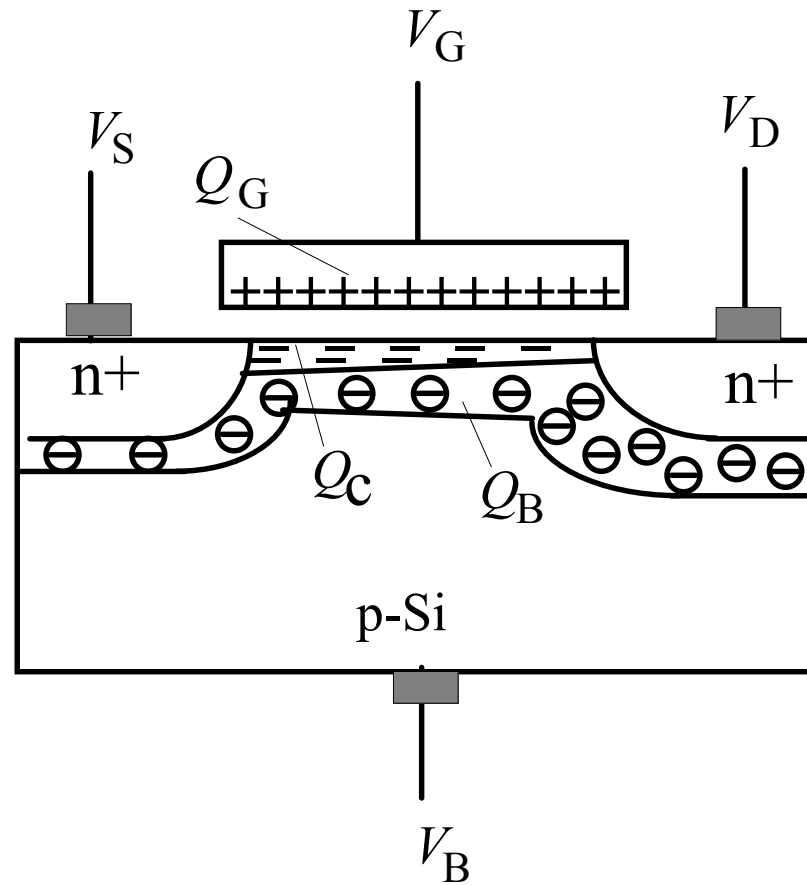
MOS晶体管的瞬态

- **MOS**晶体管的**本征电容**
- **MOS**晶体管的**寄生电容**

与MOS晶体管有关的电容



1 MOS晶体管的本征电容



Meyer电容模型

3个集总电容:

$$C_{GS} = \frac{\partial Q_{GT}}{\partial V_{GS}}, \quad C_{GD} = \frac{\partial Q_{GT}}{\partial V_{GD}}, \quad C_{GB} = \frac{\partial Q_{GT}}{\partial V_{GB}}$$

$$Q_{GT} = -(Q_{CT} + Q_{BT})$$

强反型后

$$\Delta Q_{GT} \approx -\Delta Q_{CT}$$

沟道区反型层电荷

$$C_{GS} = \frac{\partial Q_{GT}}{\partial V_{GS}}, \quad C_{GD} = \frac{\partial Q_{GT}}{\partial V_{GD}}, \quad C_{GB} = \frac{\partial Q_{GT}}{\partial V_{GB}}$$

$$\begin{aligned} Q_{CT} &= -WC_{ox} \int_0^L [V_{GS} - V_T - V_c(y)] dy \\ &= -\frac{2}{3} WLC_{ox} \frac{(V_{GS} - V_T)^3 - (V_{GS} - V_T - V_{DS})^3}{[2(V_{GS} - V_T) - V_{DS}] V_{DS}} \end{aligned}$$

$$Q_{CT} = -\frac{2}{3} WLC_{ox} \left[\frac{(V_{GS} - V_T)^3 - (V_{GD} - V_T)^3}{(V_{GS} - V_T)^2 - (V_{GD} - V_T)^2} \right]$$

线性区本征电容

$$Q_{CT} = -\frac{2}{3}WLC_{ox} \left[\frac{(V_{GS} - V_T)^3 - (V_{GD} - V_T)^3}{(V_{GS} - V_T)^2 - (V_{GD} - V_T)^2} \right]$$

$$C_{GS} = -\frac{\partial Q_{CT}}{\partial V_{GS}} = \frac{2}{3}WLC_{ox} \left\{ 1 - \frac{(V_{GS} - V_T - V_{DS})^2}{[2(V_{GS} - V_T) - V_{DS}]^2} \right\},$$

$$C_{GD} = -\frac{\partial Q_{CT}}{\partial V_{GD}} = \frac{2}{3}WLC_{ox} \left\{ 1 - \frac{(V_{GS} - V_T)^2}{[2(V_{GS} - V_T) - V_{DS}]^2} \right\}$$

$$V_{DS} \rightarrow 0, \quad C_{GS} = C_{GD} = \frac{1}{2}WLC_{ox}$$

$$C_{GB} = -\frac{\partial Q_{BT}}{\partial V_{GB}} = 0$$

饱和区本征电容

$$C_{GS} = -\frac{\partial Q_{CT}}{\partial V_{GS}} = \frac{2}{3}WLC_{ox} \left\{ 1 - \frac{(V_{GS} - V_T - V_{DS})^2}{[2(V_{GS} - V_T) - V_{DS}]^2} \right\},$$

$$C_{GD} = -\frac{\partial Q_{CT}}{\partial V_{GD}} = \frac{2}{3}WLC_{ox} \left\{ 1 - \frac{(V_{GS} - V_T)^2}{[2(V_{GS} - V_T) - V_{DS}]^2} \right\}$$

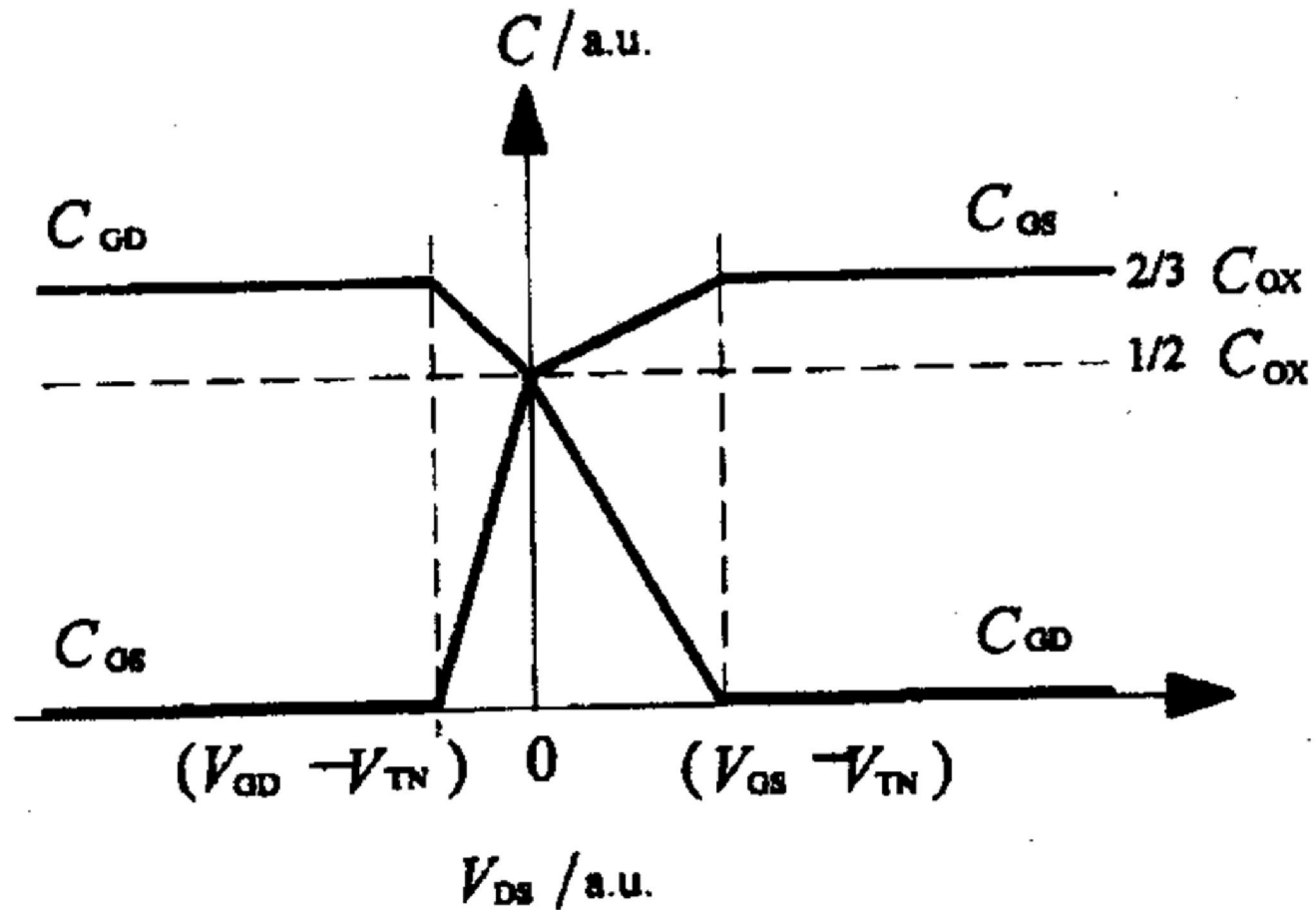
$$V_{DS} = V_{Dsat} = V_{GS} - V_T$$

$$C_{GS} = -\frac{\partial Q_{CT}}{\partial V_{GS}} = \frac{2}{3}WLC_{ox}$$

$$C_{GD} = -\frac{\partial Q_{CT}}{\partial V_{GD}} = 0$$

$$C_{GB} = -\frac{\partial Q_{BT}}{\partial V_{GB}} = 0$$

C_{GS} 和 C_{GD} 电容随 V_{DS} 的变化





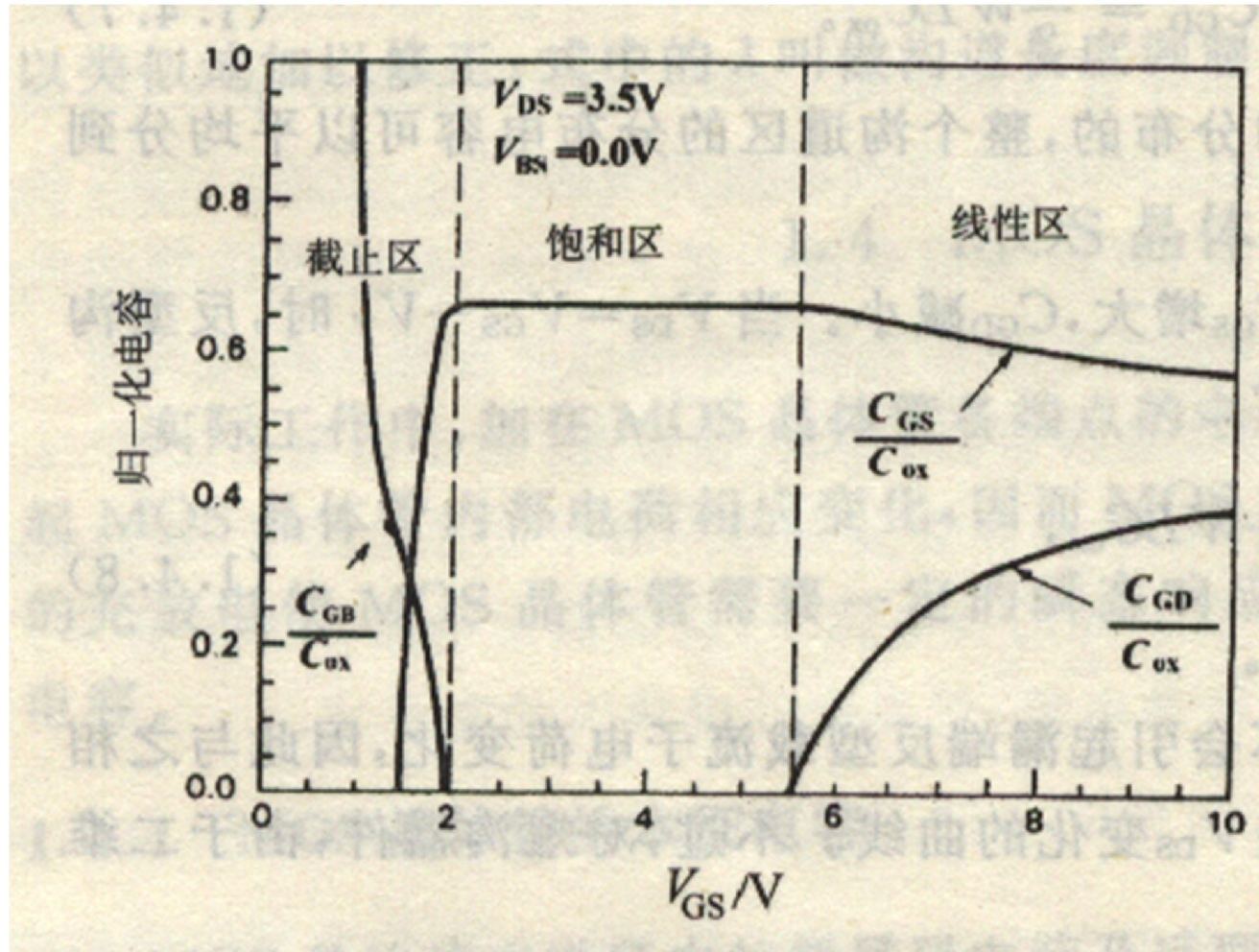
截止区的本征电容

$$Q_{GT} = -(Q_{CT} + Q_{BT}) = -Q_{BT}$$

$$C_{GB} = -\frac{\partial Q_{BT}}{\partial V_{GB}} = \frac{WLC_{ox}}{\left[1 + 4(V_{GS} - V_{FB}) / \gamma^2\right]^{1/2}}$$

$$C_{GS} = C_{GD} = 0$$

本征电容随 V_{GS} 的变化

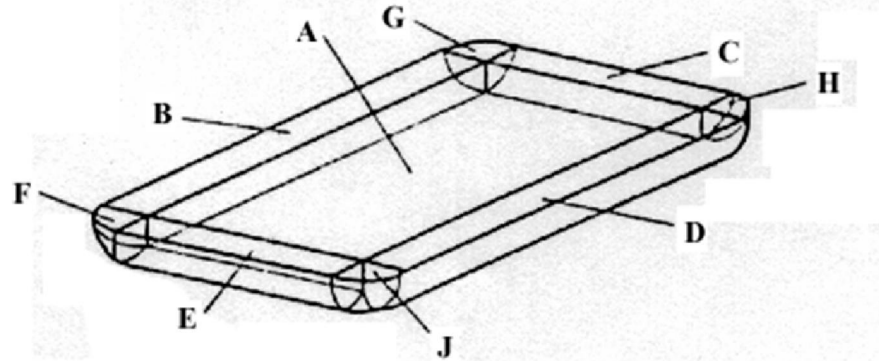


本征电容的简单分区模型

工作区	C_{GB}	C_{GS}	C_{GD}
截止区	$WLCox$	0	0
线性区	0	$1/2 WLCox$	$1/2 WLCox$
饱和区	0	$2/3 WLCox$	0

2 MOS晶体管的寄生电容

源、漏区pn结电容



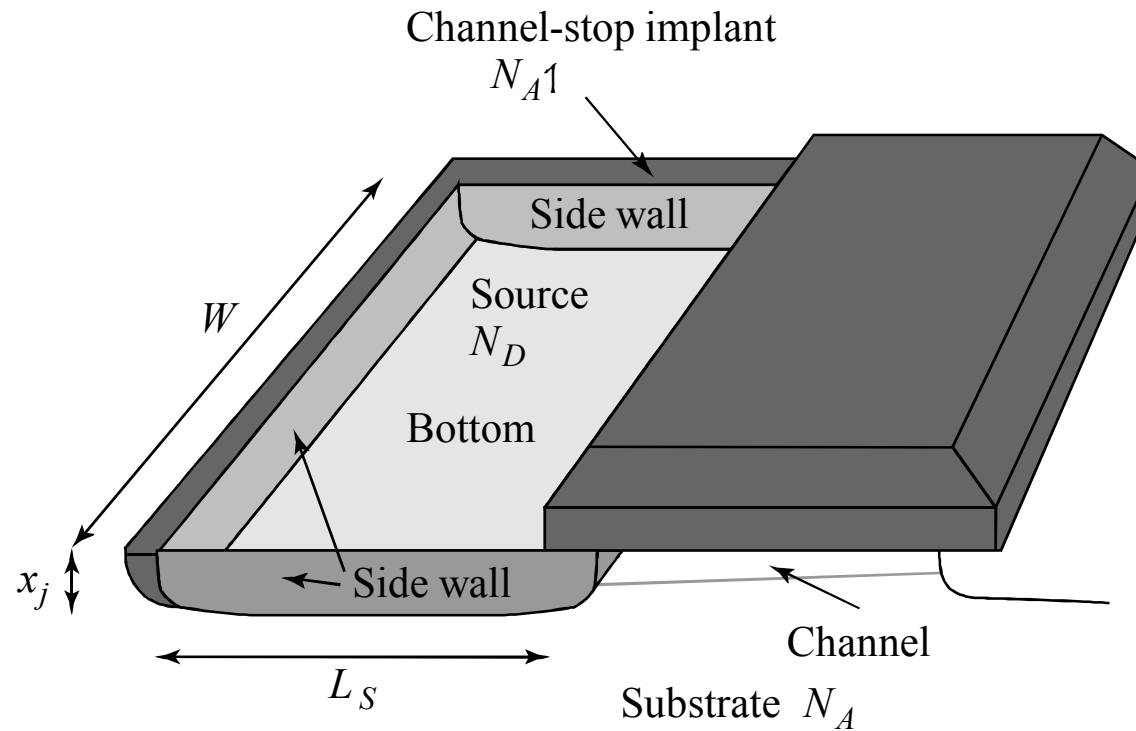
$$C_{SB} = A_S C_{jA} + P_S C_{jP} + nC_{jc}$$

$$C_{DB} = A_D C_{jA} + P_D C_{jP} + nC_{jc}$$

$$C_{jA} = C_{j0} \left(1 + \frac{V}{V_{bi}} \right)^{-1/2}$$

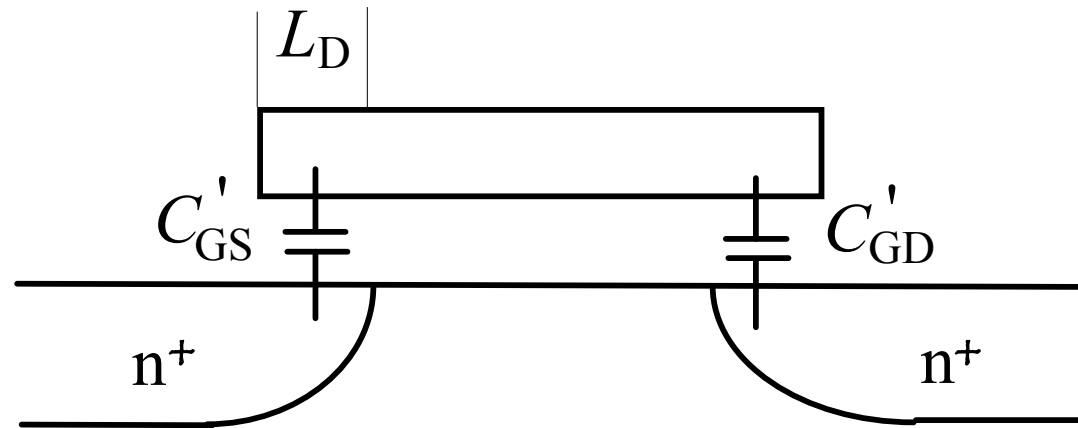
$$C_{jP} = C_{jp0} \left(1 + \frac{V}{V_{bi}} \right)^{-1/3}$$

源、漏区pn结电容



$$C_{diff} = C_{bottom} + C_{sw} = C_j \times AREA + C_{jsw} \times PERIMETER$$
$$= C_j L_S W + C_{jsw} (2L_S + W)$$

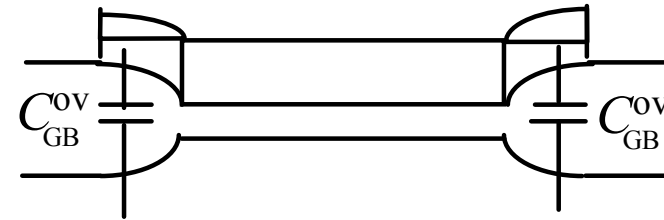
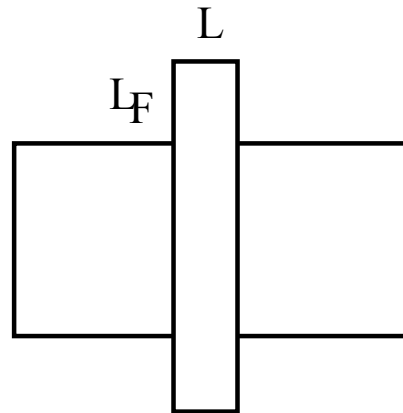
栅-源、栅-漏覆盖电容



$$C'_{GS} = C'_{GD} = WL_D C_{ox}$$

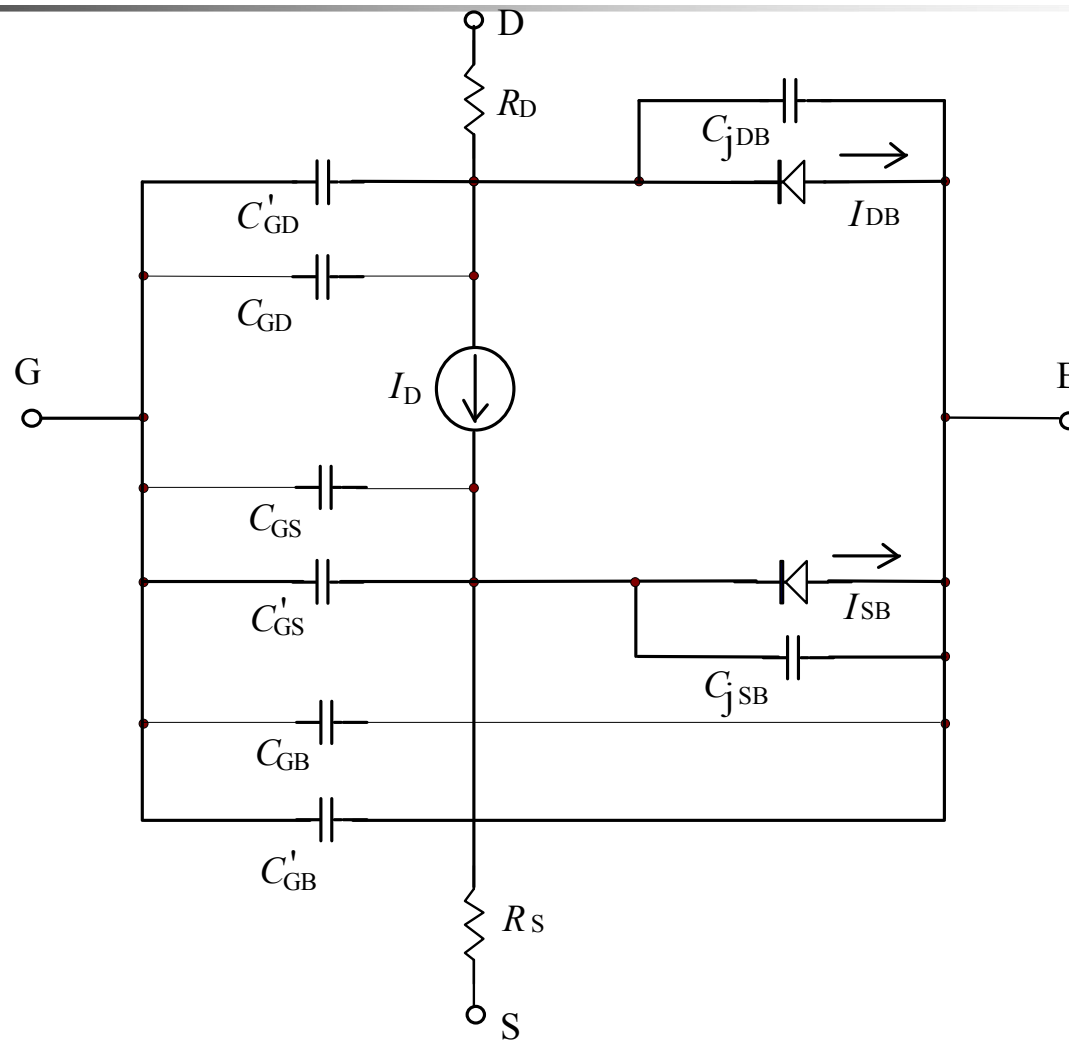
$$C'_{GS} = WC_{GS0}, \quad C'_{GD} = WC_{GD0}$$

栅-衬底覆盖电容



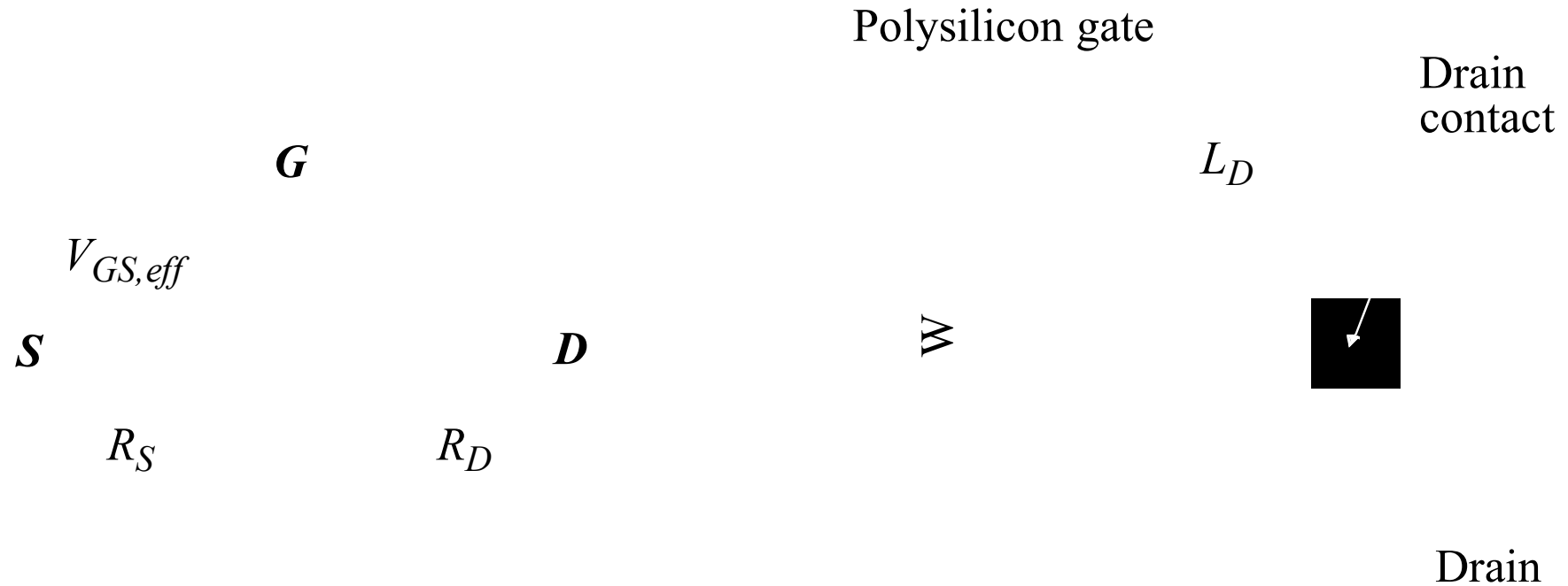
$$C_{GB}' = L L_F C_{oxF} = LC_{GB0}$$

MOS晶体管的瞬态分析模型

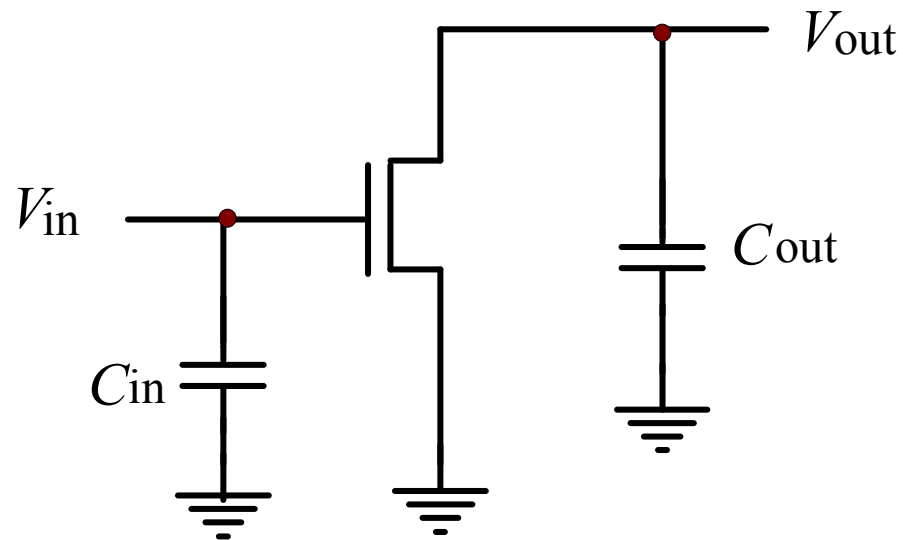




Parasitic Resistances



MOSFET电容的简化模型



$$C_{in} \approx WLC_{ox}$$

$$C_{out} \approx C_{DB}$$

0.25 μm CMOS Capacitances

$$C_{jA} = C_{j0} \left(1 + \frac{V}{V_{bi}}\right)^{-1/2}$$

$$C_{jP} = C_{jP0} \left(1 + \frac{V}{V_{bi}}\right)^{-1/3}$$

	C_{ox} (fF/ μm^2)	C_o (fF/ μm)	C_j (fF/ μm^2)	m_j	ϕ_b (V)	C_{jsw} (fF/ μm)	m_{jsw}	ϕ_{bsw} (V)
NMOS	6	0.31	2	0.5	0.9	0.28	0.44	0.9
PMOS	6	0.27	1.9	0.48	0.9	0.22	0.32	0.9

- **W/L=0.36 μm /0.25 μm 的NMOS ($L_{D,S}=0.625\mu$)**
- 根据设计规则，计算出栅和漏端的电容

$$C_G = WLC_{ox} = 0.54\text{fF}, \quad C'_{GD} = C'_{GS} = WC_o = 0.11\text{fF}, \quad \therefore C_{in} = 0.76\text{fF}$$

$$C_{bottom} = C_j WL_D = 0.45\text{fF}, \quad C_{sw} = C_{jsw}(W + 2L_D) = 0.45\text{fF}, \quad \therefore C_{out} = 0.9\text{fF}$$

- 如果考虑反偏电压和适当的版图优化，二者基本相等，漏端电容甚至更小些